

# $^{163}\text{Ho}$ implantation in the HOLMES experiment

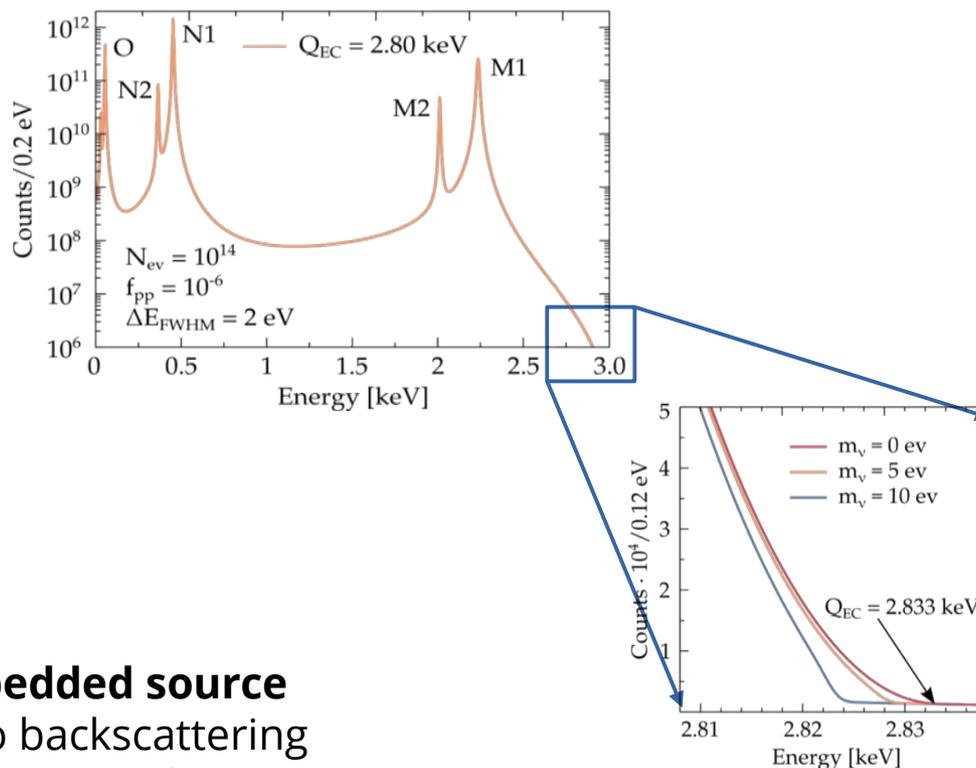
**Mariia Fedkevych**  
for the HOLMES collaboration  
**9.06.2022**



# Direct neutrino mass measurement approaches

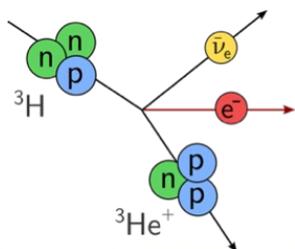
## General requirements

- energy resolution order  $\sim$ eV or below (comparable with  $m_\nu$ )
- high statistics in the end-point region of beta decay / EC capture
  - low Q-value (stat  $\sim 1/Q^3$ )
  - high activity/efficiency of the source
- small systematic effects



## External source

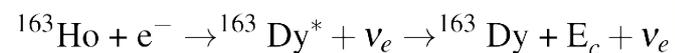
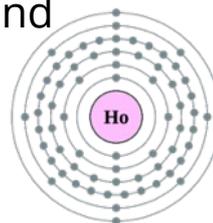
- + high statistics
- + high energy resolution (below eV)
- systematics due to the source (energy loss)
- systematics due to decay to excited states
- background



**PROJECT 8**

## Embedded source

- + no backscattering
- + no energy loss in source
- + no solid state excitation
- + no atomic/molecular final state effects
- + good energy resolution ( $\sim$ eV)
- limited statistics
- systematics due to pile-up
- background



# HOLMES TES detector

## Requirements

- energy resolution  $\Delta E \sim 1 \text{ eV}$ , time  $\Delta t \sim 1 \mu\text{s}$
- $6.5 \times 10^{13}$  nuclei/det,  $A(\text{EC}) \sim 300 \text{ Bq/det}$  (challenging!)
- 1000 channels array:  $6.5 \times 10^{16}$  total nuclei ( $\approx 18 \mu\text{g}$ )
- $O(10^{13})$  events / year, data taking  $\sim 3$  years
- pile up fraction  $f_{pp} \approx A \times \Delta t = 3 \times 10^{-4}$

## HOLMES technique

- Au absorber with  $^{163}\text{Ho}$  inside coupled to TES Mo/Cu ( $T_c \sim 100 \text{ mK}$ ) thermometer
- Ho sandwiched between two  $1 \mu\text{m}$  thick gold layers for a total electron containment
- very steep  $R$  vs  $T$  dependency in transition region
- fast detectors to reduce pile-up

- adjustable rise time  $\sim L/R$
- decay time dependent on detector characteristics  $C/G$

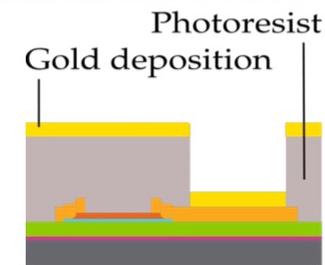
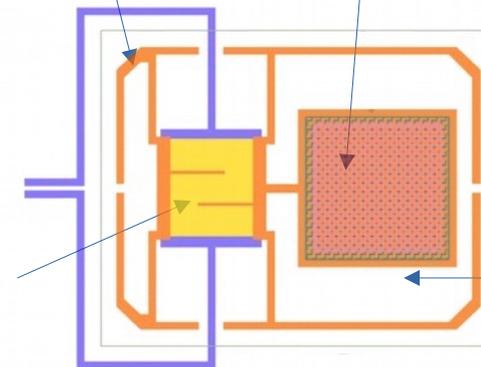
- TESs made by NIST
- Ho implantation in Genoa
- final machining and cryogenic operation in Milan

Cu structure for thermalization (high G)

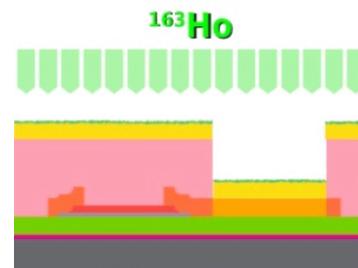
Au absorber

Mo/Cu TES

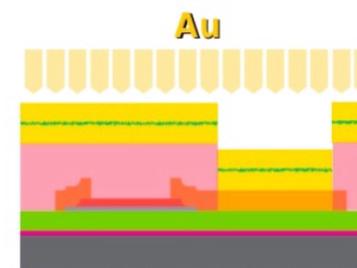
$\text{Si}_2\text{N}_3$  membrane



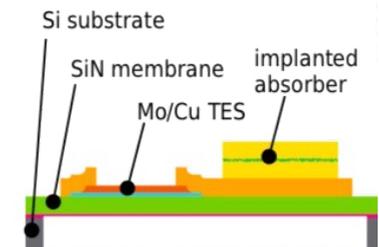
NIST



ion implantation



full encapsulation



photoresist lift-off and SiN membrane release

INFN Genoa

Milano-Bicocca U.

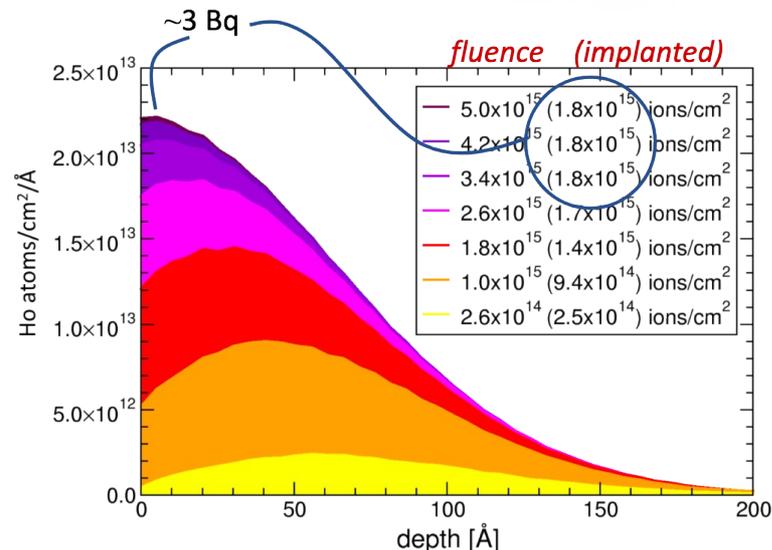
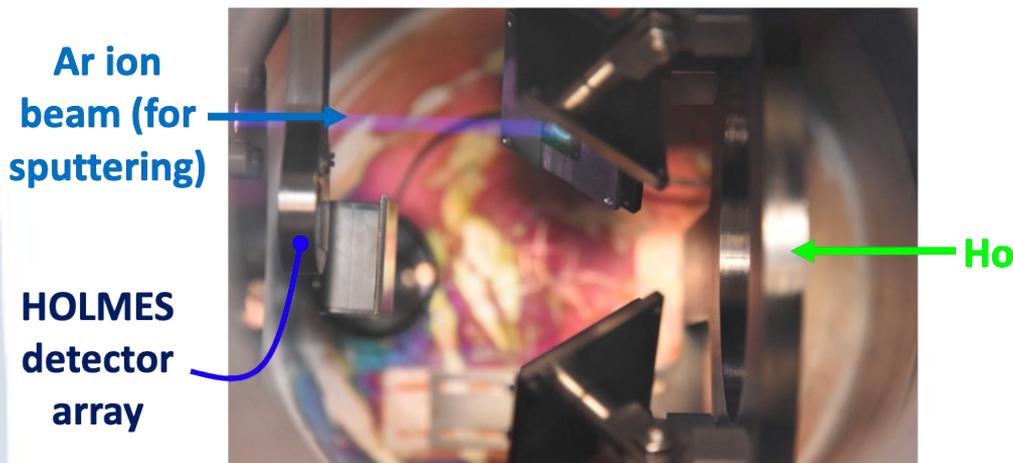
[A. Giachero et al., 10.1109/TASC.2021.3051104](https://doi.org/10.1109/TASC.2021.3051104)

# Au co-evaporation

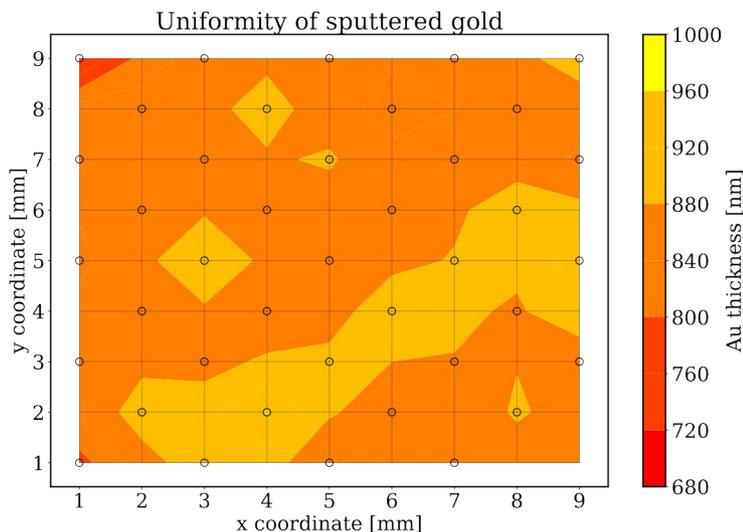
Ho concentration in absorbers saturates due to incoming Ho sputtering deposited Ho.

→ compensation by a Au co-evaporation.

→ full encapsulation by deposition of final 1  $\mu\text{m}$  Au layer to avoid Ho oxidation



A dedicated target chamber designed and commissioned in Milano Bicocca:



- uniformity check: sputtering Au for ~22 hours on a Si slab 1 × 1 cm<sup>2</sup> with a drilled mask  
Thickness with profilometer:  
d = 865 ± 40 nm
- Deposition rate > 50 nm/hours  
→ 1  $\mu\text{m}$  Au can be deposited in around 20 hours.

[See talk of M. Borghesi](#)

# $^{163}\text{Ho}$ production and purification

Er 162 0.139	Er 163 75 m	Er 164 1.601	Er 165 10.3 h	Er 166 33.503	Er 167 2.3 s, 22.869
Ho 161 6.7 s, 2.5 h	Ho 162 68 m, 15 m	Ho 163 1.1, 4570 a	Ho 164 37 m, 29 m	Ho 165 100	Ho 166 1200 a, 26.80 h
Dy 160 2.329	Dy 161 18.889	Dy 162 25.475	Dy 163 24.896	Dy 164 28.260	Dy 165 1.3 m, 2.35 h

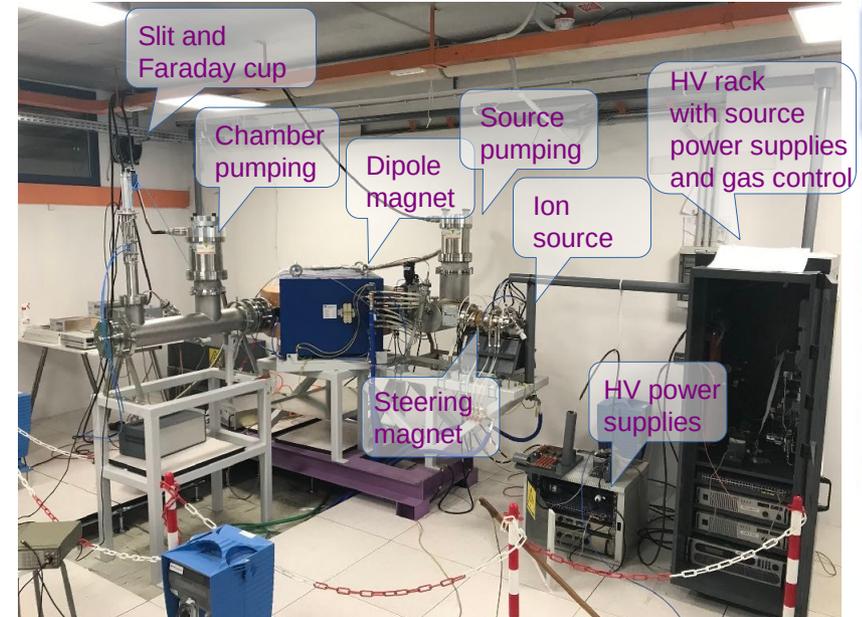
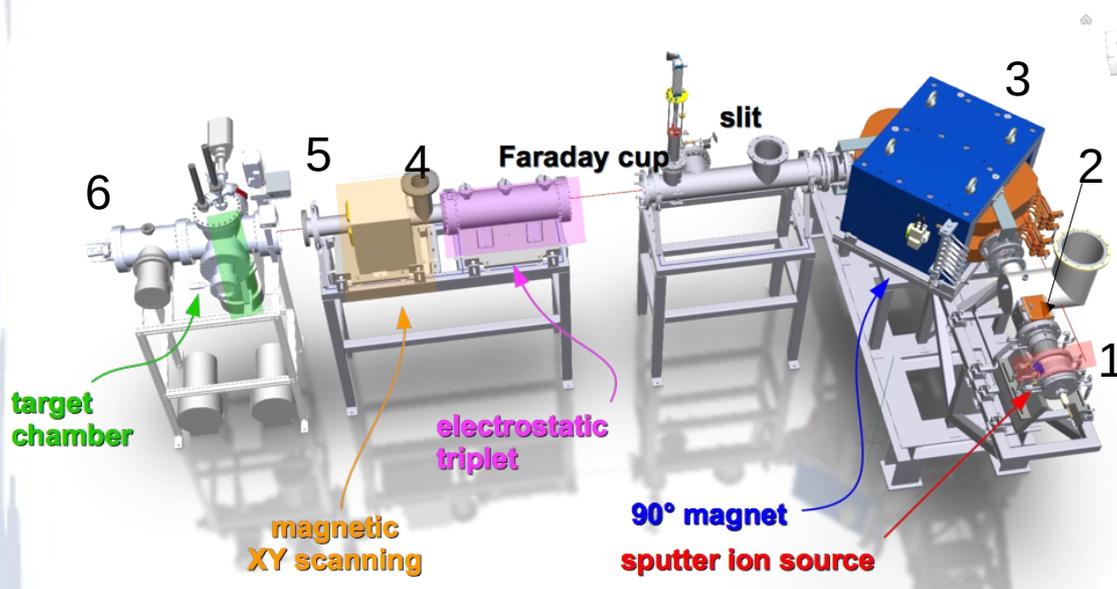
- $^{163}\text{Ho}$  produced by neutron irradiation of  $\text{Er}_2\text{O}_3$  enriched (30%) in  $^{162}\text{Er}$  at the Institut Laue-Langevin (ILL, Grenoble, France). Thermal neutron flux at ILL:  $1.3 \times 10^{15} \text{ n/cm}^2/\text{s}$ .  $^{162}\text{Er}(n,\gamma)^{163}\text{Er}$  ( $\sigma_{\text{thermal}} \sim 20 \text{ b}$ ),  $^{163}\text{Er} + e^- \rightarrow ^{163}\text{Ho} + \nu_e$  ( $\tau_{1/2} \sim 75\text{min}$ ).

## • Contaminants:

1. Other elements (residual Er, rare earth contaminants, decay product, etc...)
  - chemical purification (PSI);
2. Holmium isotopes, in particular  $^{166\text{m}}\text{Ho}$  ( $\beta^-$ ,  $Q = 1856 \text{ keV}$ ,  $\tau_{1/2} \sim 1200 \text{ y}$ )
  - $A(^{166\text{m}}\text{Ho})/A(^{163}\text{Ho}) \sim O(1/1000)$
  - isotope separation with ion implanter (INFN Genoa).

- 110 MBq of purified  $^{163}\text{Ho}$  available at Genoa ( $\approx 250 \text{ kBq}$  of  $^{166\text{m}}\text{Ho}$ ) in oxide form ( $\text{Ho}_2\text{O}_3$ ) in acid solution ( $\text{pH} < 4$ ) to avoid adhesion to the vial wall. The Er recovered from the purification procedure is available to produce other 80 MBq of  $^{163}\text{Ho}$ .

# Ion mass separation & implantation

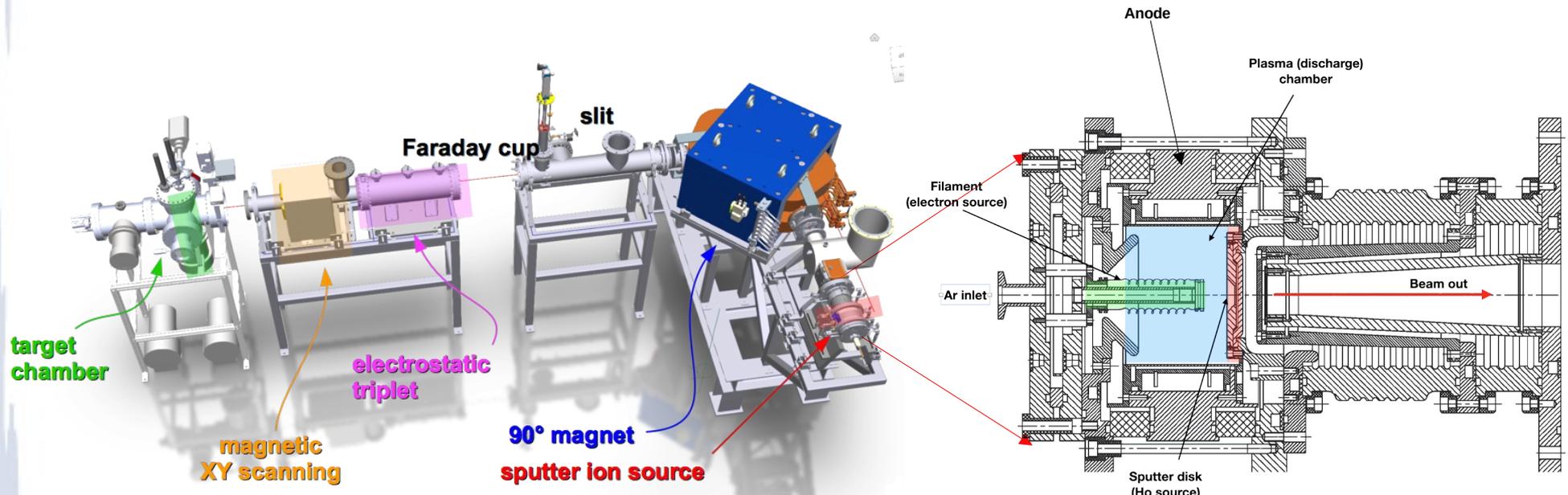


Ion implanter @ Genoa removes contamination of holmium isotopes different from  $^{163}\text{Ho}$  & other impurities. Reduced setup has been commissioned.

Components:

1. **an argon sputter ion source** with an acceleration section to reach the beam energy of 50 keV (~50 nm implantation depth)
2. **a steering magnet** right after the ion source to correct the vertical component of the beam direction
3. **a magnetic/electrostatic mass analyzer** with magnetic field until 1.1 Tesla
4. **a focusing electrostatic triplet** (not yet mounted);
5. **a magnetic scanning stage** (not yet mounted);
6. **a target chamber** (not yet mounted).

# Ion mass separation & implantation

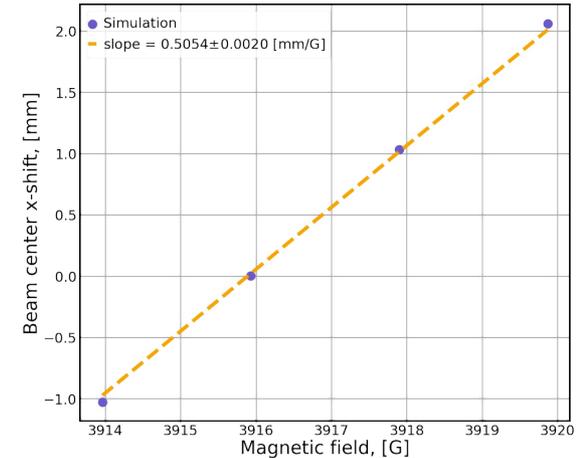
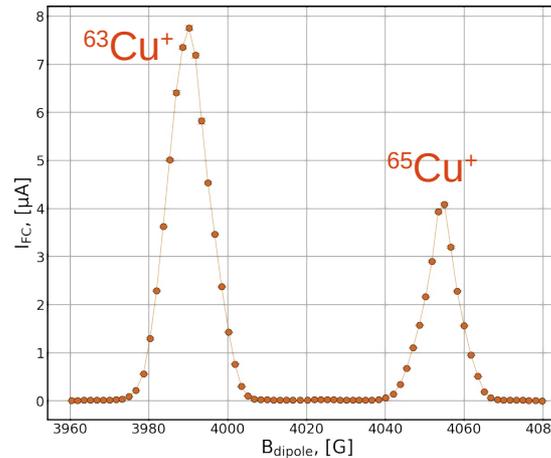


Penning sputter ion source (Danfysik):

- **Ar inlet:** controlled argon flow enters inside the discharge chamber. Argon is ionized and argon plasma burns inside the chamber
- **Filament:** electrons are emitted by thermionic effect. The electrons ionize argon and sputtered materials
- **Sputter disk target** with tunable electrical potential (max 600 V) to attract ions
- **Acceleration section:** ions pass through the hole in the sputter disk and are accelerated in this region (max 50 kV)
- all parts are water cooled but the sputter target reaches temperatures  $>1000$  °C

# Ion peak separation

- use *elegant*<sup>1</sup> simulation package for our beamline
- from simulation we found @63 a.m.u., 1G corresponds 0.51 mm
- measured 63 G separation between <sup>63</sup>Cu<sup>+</sup> and <sup>65</sup>Cu<sup>+</sup> peaks corresponds to ≈ 32.5 mm evaluated with MC simulation



- From Danfysik expectation, dipole should have a dispersion  $D(p)=2060\text{mm}$  at image plane where the slit is.

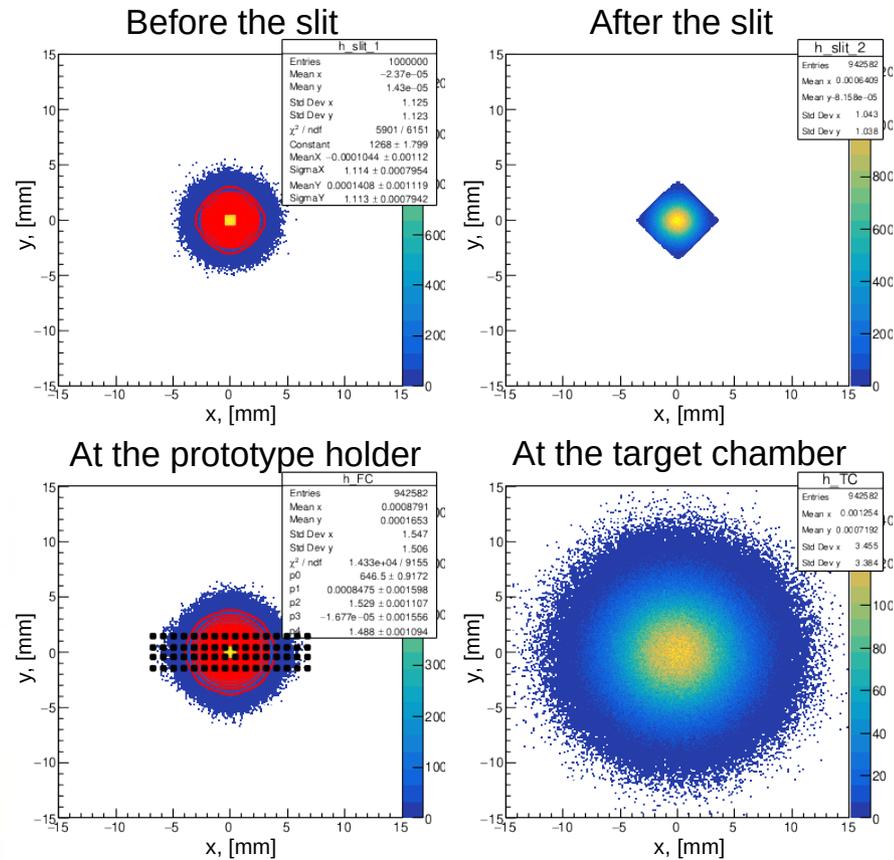
$$\Delta x = D(p) \frac{\Delta p}{p}$$

$\Delta p/p$  @25keV (current nominal acceleration) for 65/63 a.m.u. = 1.575%  
 $2060 \text{ mm} \times 0,01575 \approx 32.5 \text{ mm} \rightarrow$  it seems Danfysik results are well-reproduced.

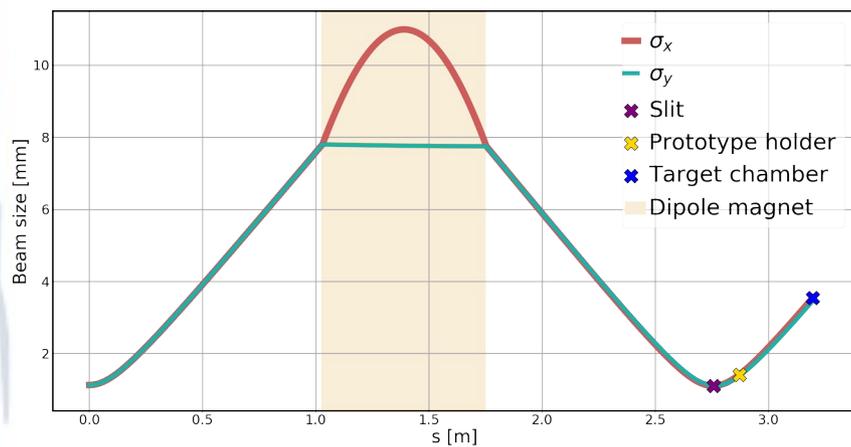
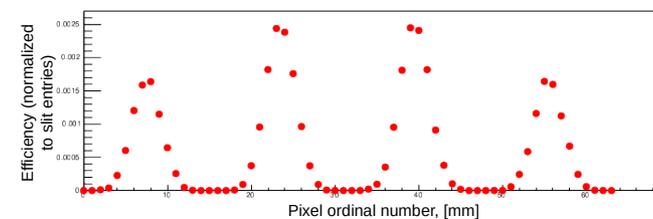
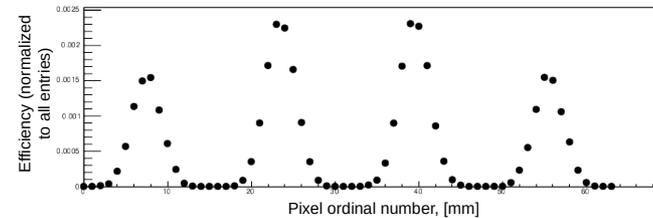
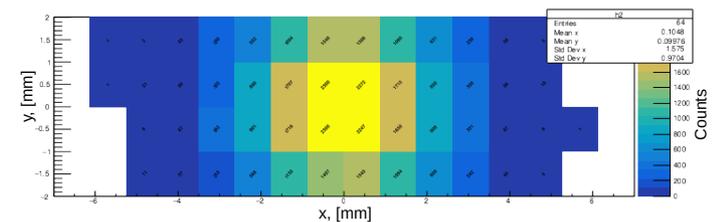
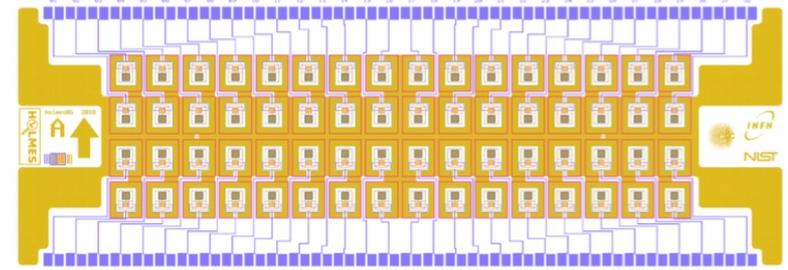
- 31 G/a.m.u. @63amu corresponds to 15 mm/a.m.u. evaluated with simulations  $\rightarrow$  extrapolation to the ROI gives 15.5 mm separation between 163/166 a.m.u. With beam size  $\sim 1.5 \text{ mm}$  better than  $10\sigma$  separation

<sup>1</sup>an open-source code from APS for simulating rings, linacs, and beam transport systems, and for tracking particle beams, <https://www.aps.anl.gov/Accelerator-Operations-Physics/Software>

# Geometrical efficiency simulations



Simulated implantation efficiency in 4x16 array of 200  $\mu\text{m}$  x 200  $\mu\text{m}$  absorbers on a holder

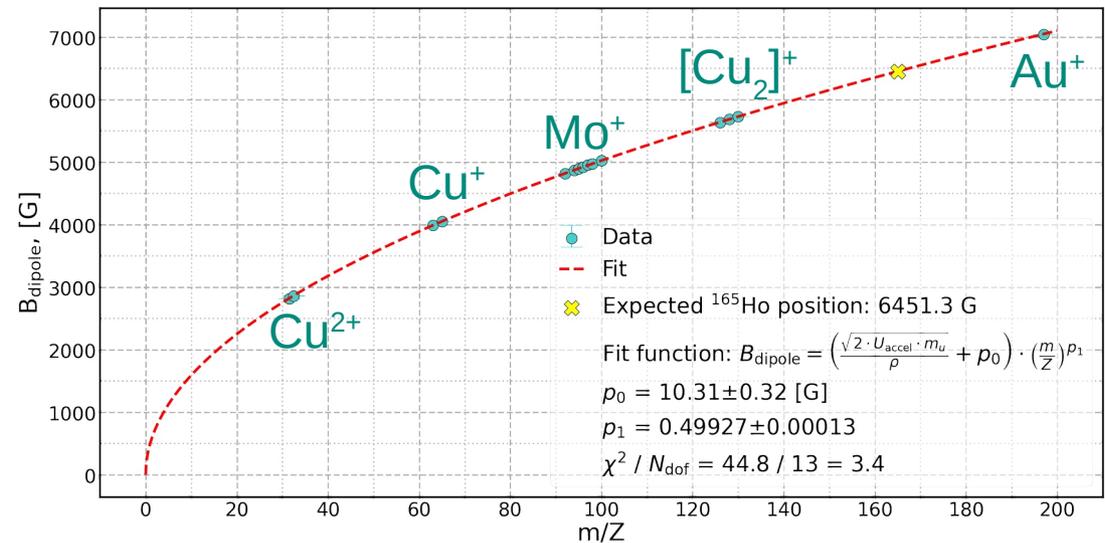
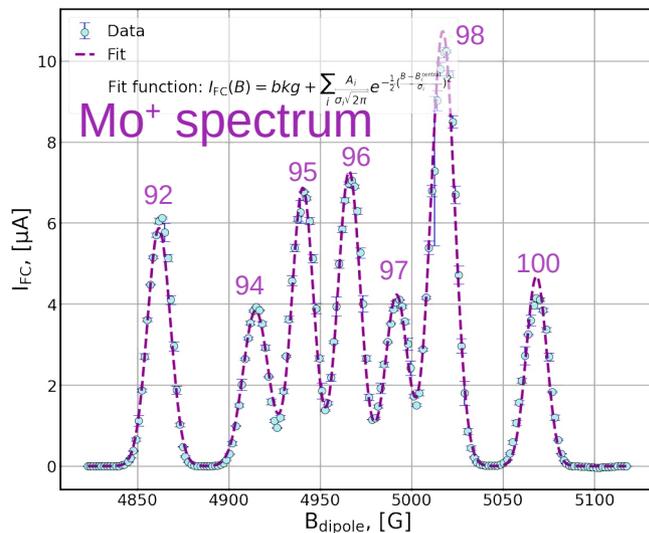


At the target chamber where the final array will be placed the beam will be more de-focused so more uniform implantation

Orient the array in vertical direction during implantation and swipe with beam steering for better uniformity

# Dipole magnet calibration

- The dipole magnetic field is independently measured with a gauss probe
- Different materials inside the chamber (e.g. Cu/Au from sputter target/holder, Mo from the anode *etc.*) allow for a magnetic field vs mass-to-charge ratio calibration



Natural abundances:

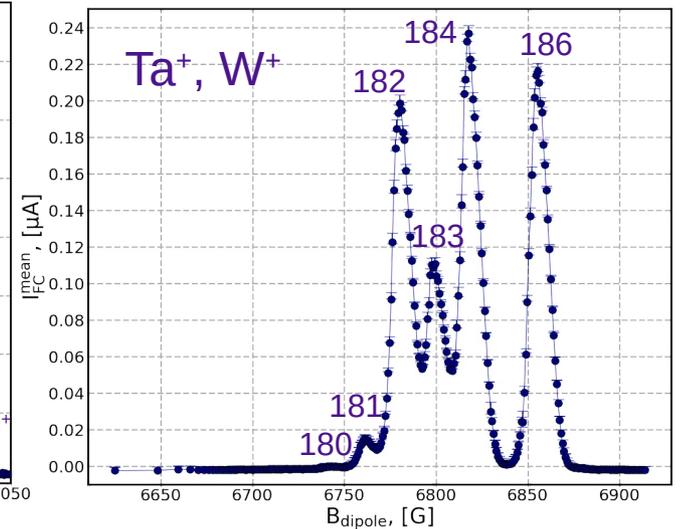
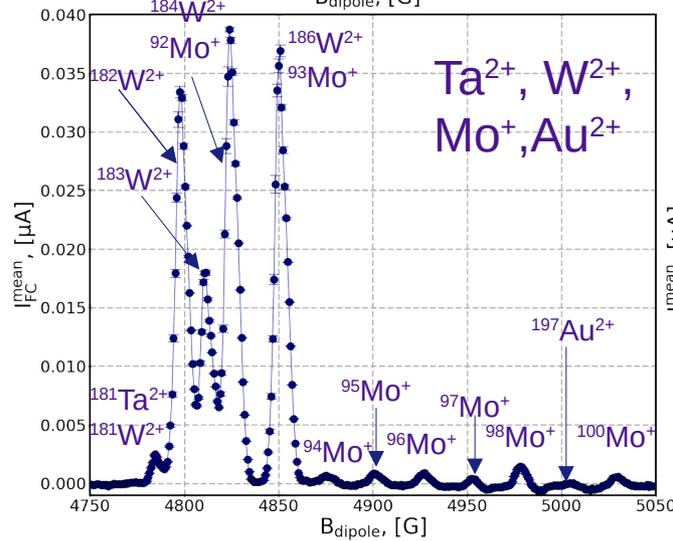
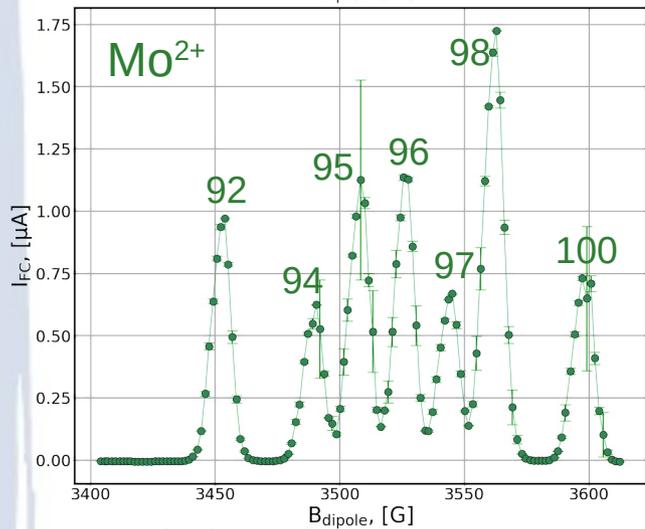
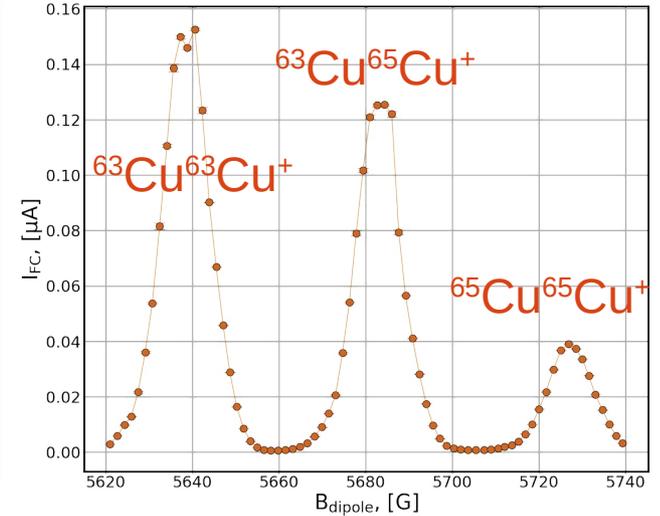
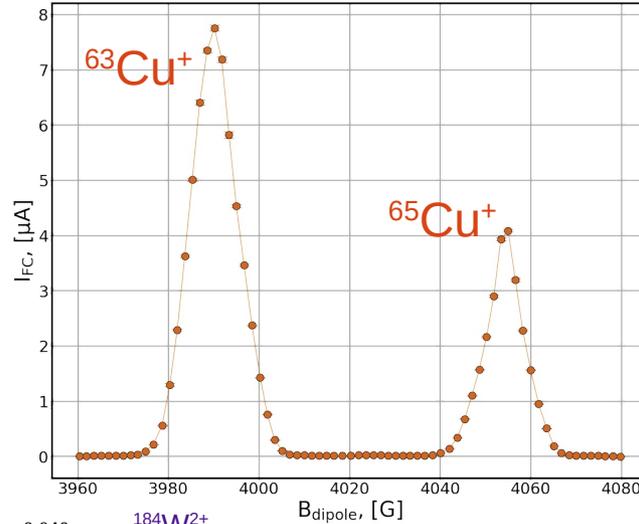
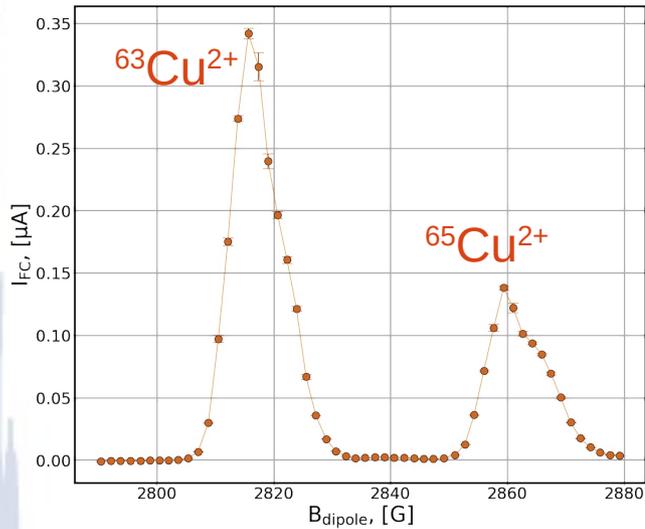
<sup>63</sup>Cu: 69.17%    <sup>65</sup>Cu: 30.83%

<sup>92</sup>Mo: 14.84%    <sup>94</sup>Mo: 9.25%    <sup>95</sup>Mo: 15.92%    <sup>96</sup>Mo: 16.68%    <sup>97</sup>Mo: 9.55%    <sup>98</sup>Mo: 24.13%    <sup>100</sup>Mo: 9.63%

<sup>197</sup>Au: 100%

# Currents of different ion species

The source produces also multiple-ionized and dimeric ions from the same material, which can also be used for calibration

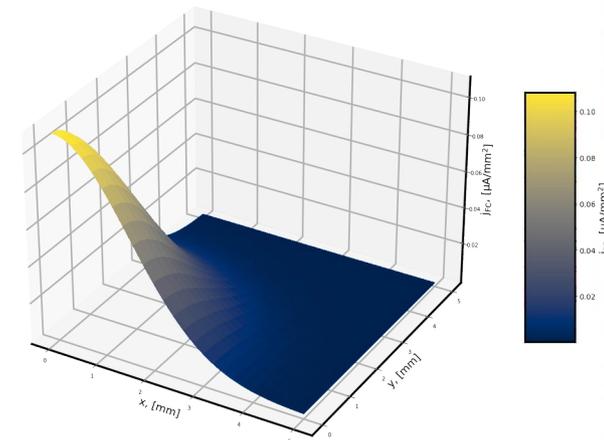
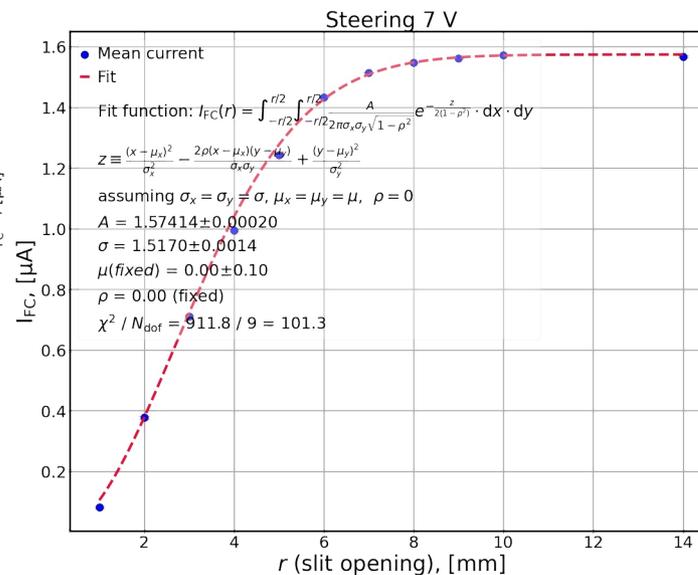
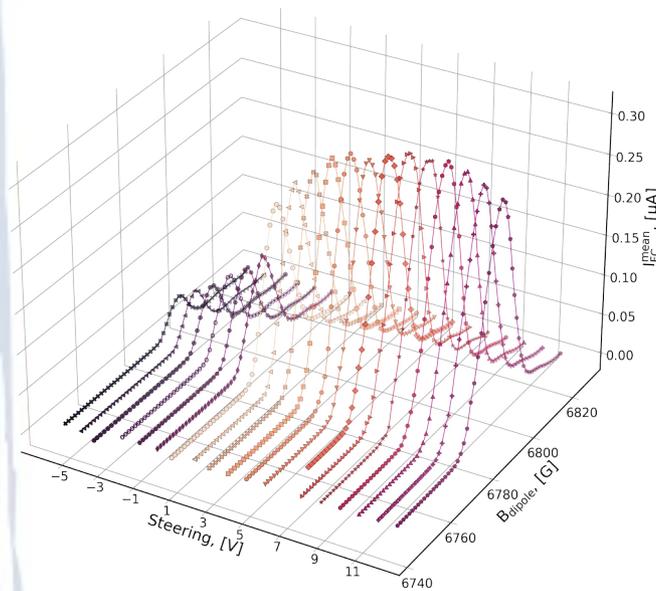


Natural abundances:

$^{63}\text{Cu}$ : 69.17%     $^{65}\text{Cu}$ : 30.83%  
 $^{92}\text{Mo}$ : 14.84%     $^{94}\text{Mo}$ : 9.25%     $^{95}\text{Mo}$ : 15.92%     $^{96}\text{Mo}$ : 16.68%     $^{97}\text{Mo}$ : 9.55%     $^{98}\text{Mo}$ : 24.13%     $^{100}\text{Mo}$ : 9.63%  
 $^{180}\text{Ta}$ : 0.012%     $^{181}\text{Ta}$ : 99.988%  
 $^{180}\text{W}$ : 0.12%     $^{182}\text{W}$ : 26.50%     $^{183}\text{W}$ : 14.31%     $^{184}\text{W}$ : 30.64%     $^{186}\text{W}$ : 28.41%

# Beamline commissioning

- Steering magnet allows to center the beam, scan the peak with magnet to find maximum. Misalignment depends on ion mass and charge, other studies and simulation are in progress.
- Centering around the peak maximum with dipole and steering magnet, measure current for different slit apertures. Fitting with 2D symmetric Gaussian cumulative function we estimated a beam size  $\sigma \approx 1.5$  mm. More advanced fit would take into account a finite 2-dimensional slit aperture

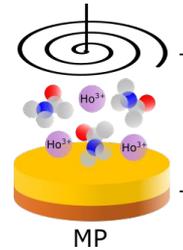


# Targets with $^{165}\text{Ho}$ compound on surface (PSI)

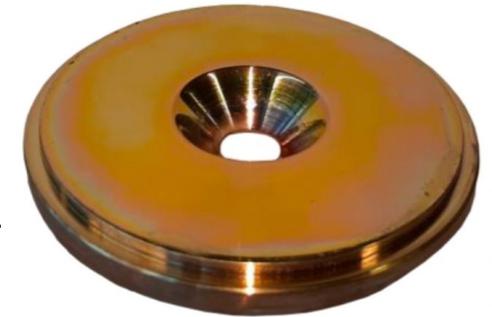
## Molecular plating (MP)



PSI



- deposition of Ho complexes in an organic solvent at high voltages with high uniformity and efficiency

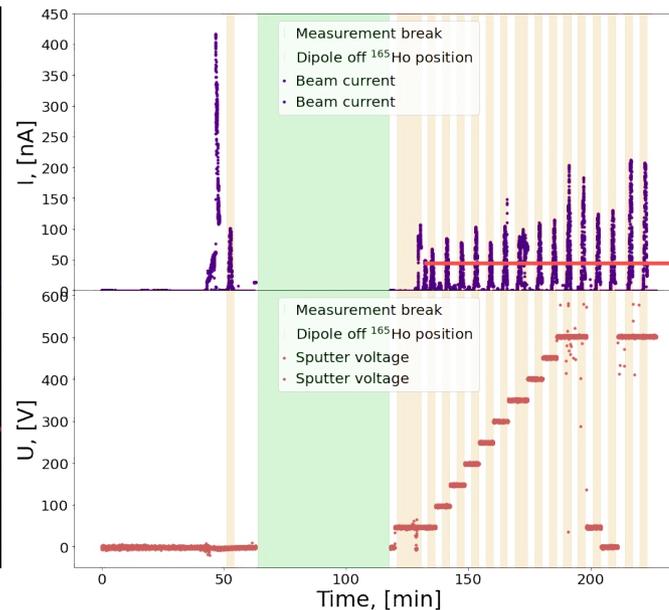
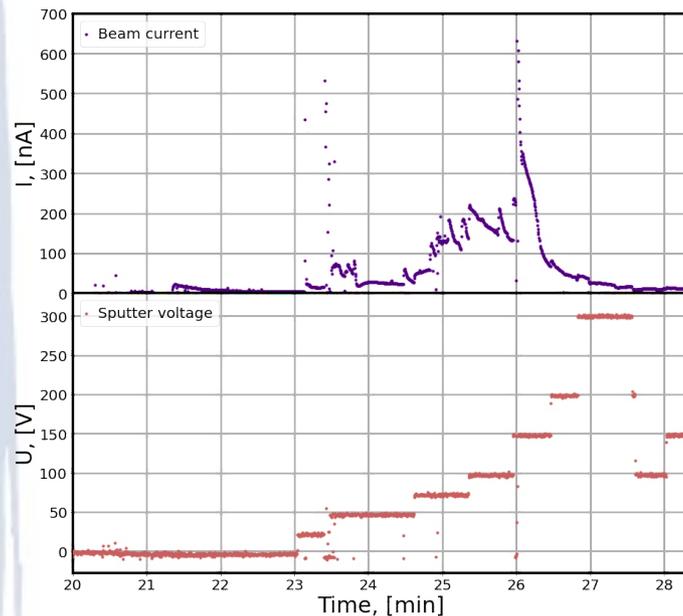


Sample 1:

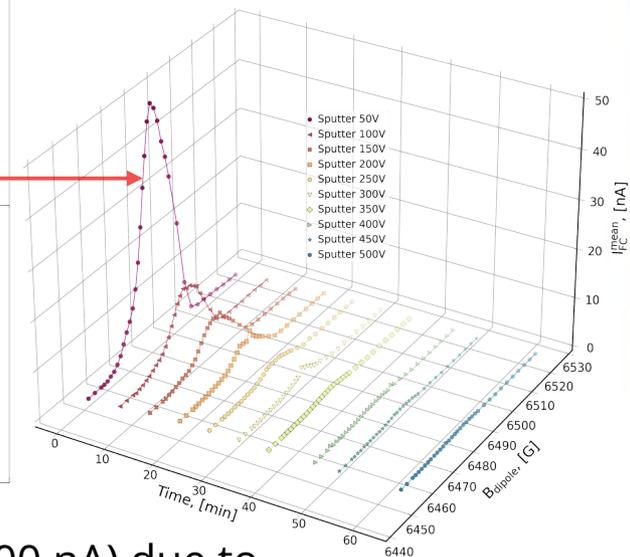
Au 100 nm sticking layer  
on Cu bulk

Sample 2:

Au 100 nm + Ti 18 nm sticking layer  
on Cu bulk



$^{165}\text{Ho}$  peak



- No  $^{165}\text{Ho}^+$  current with sputter off
- Switching on the sputter, get  $^{165}\text{Ho}^+$  current  $\text{O}(100 \text{ nA})$ , spike  $\sim 700 \text{ nA}$  and then vanishing in few minutes

- Initial  $^{165}\text{Ho}^+$  current spike  $\text{O}(400 \text{ nA})$  due to filament warming, then from  $\sim 50 \text{ nA}$  vanishing over 30 min

# Targets with $^{165}\text{Ho}$ compound on surface (PSI)

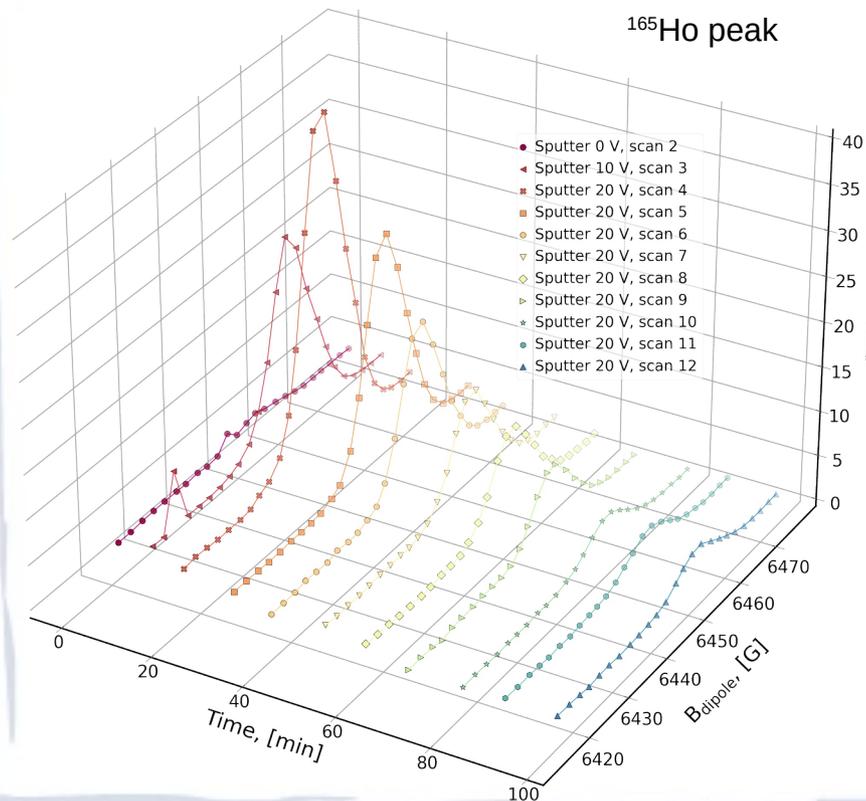
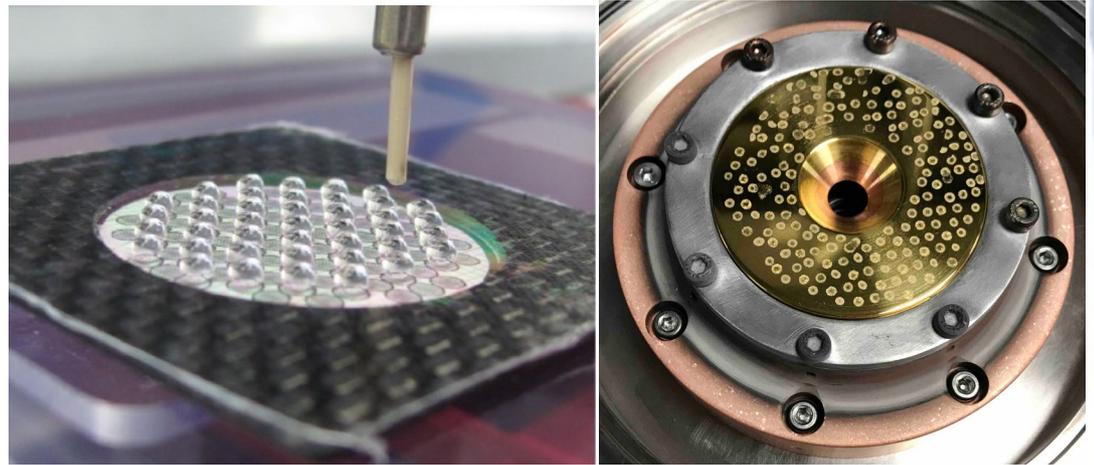
## Drop-on-demand inkjet printing (IJP)



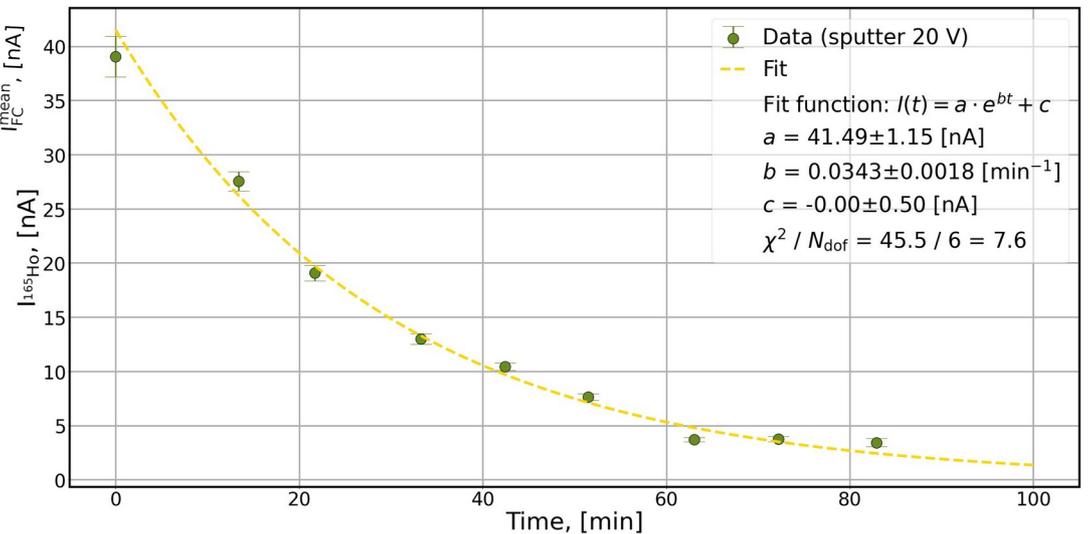
PSI

- put droplets of solution containing compound and let solvent evaporate to deposit the dissolved compound

Au 100 nm + 20 nm Ti  
sticking layer on Cu bulk



- Initial  $^{165}\text{Ho}^+$  current  $\sim 40$  nA
- Exponential current decay over  $O(2 \text{ h})$

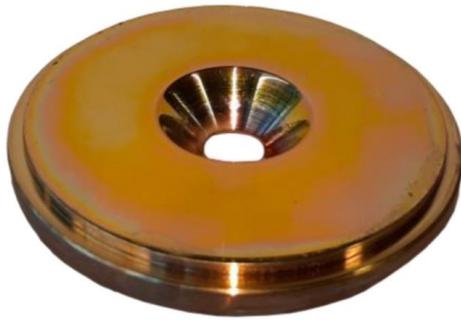


# Targets with $^{165}\text{Ho}$ compound on surface (PSI)

## Molecular plating (MP)



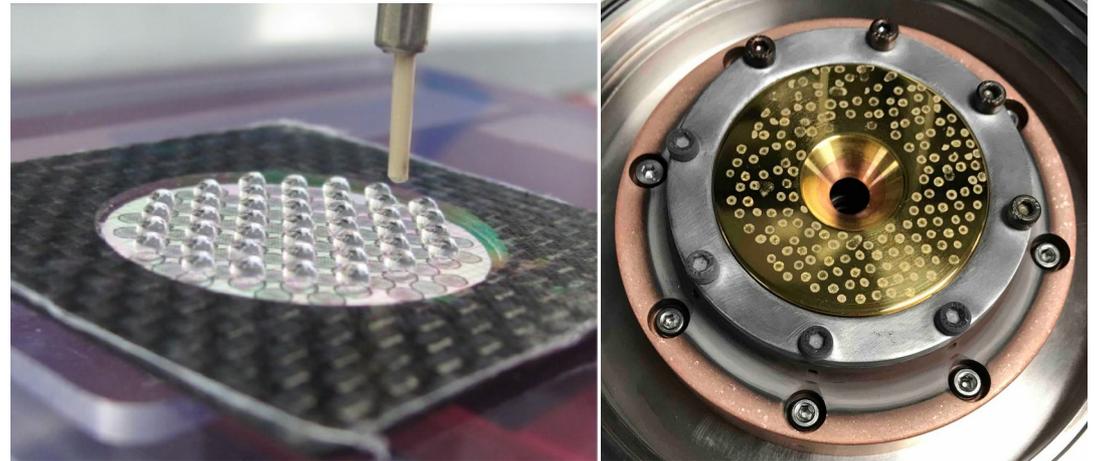
PSI



## Drop-on-demand inkjet printing (IJP)



PSI



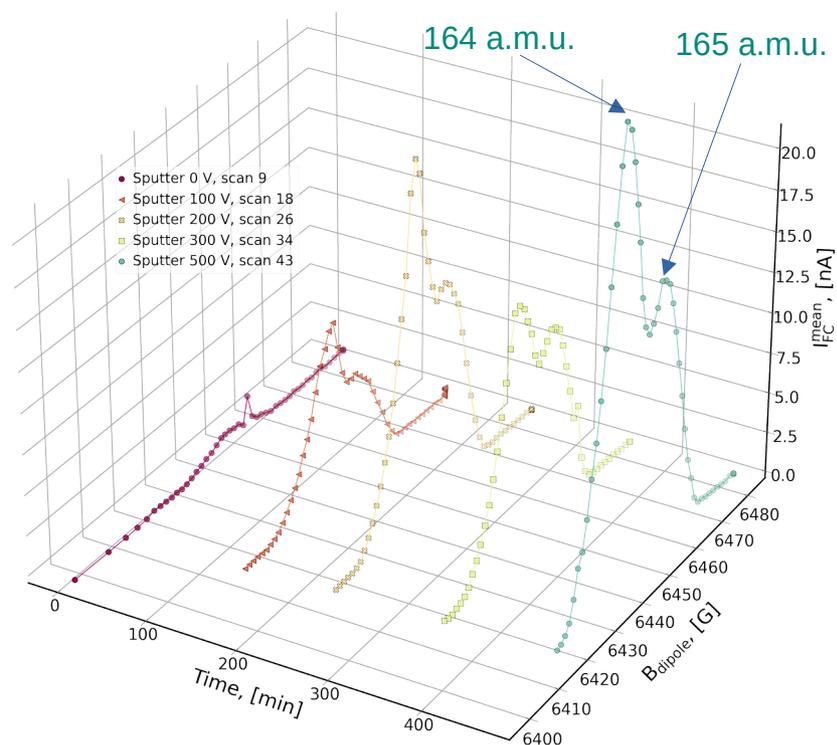
- + Safe fabrication
- + Possibility to use various materials to optimize properties
- Holmium as thin fragile film on surface

# Sintered targets (UniGe)

**Sinter  
metallic Ho 5%,  
Ti 36%, Ni 41%,  
Sn 18%  
on Cu holder**



- Ho chips mixed with other fine-grained powders ( $\leq 40 \mu\text{m}$ ) of Ti, Ni, Sn on a copper support and pressed at  $350 \text{ bar/cm}^2$
- baked at  $950 \text{ }^\circ\text{C}$  and at  $10^{-4} \text{ mbar}$  (low-oxygen environment) for 2 days  
(create intermetallic compounds  $\text{Ti}_2\text{Ni}_2\text{Sn}/\text{HoNiSn}$ )



- Parasitic peak at 164 a.m.u. (presumably from  $^{48}\text{Ti}^{116}\text{Sn}^+$ ) along with 165 a.m.u.

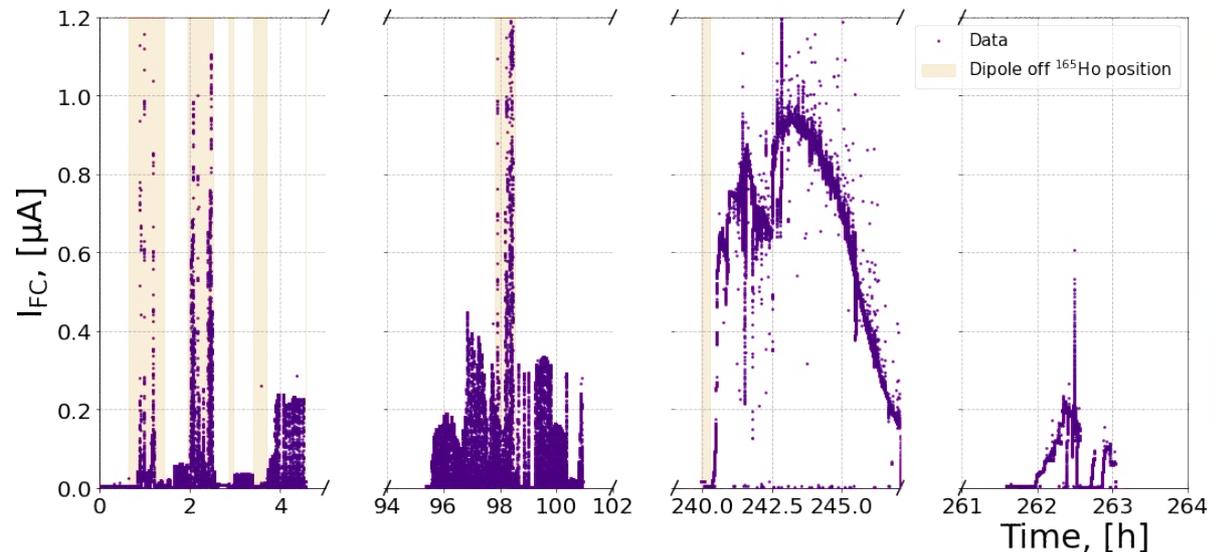
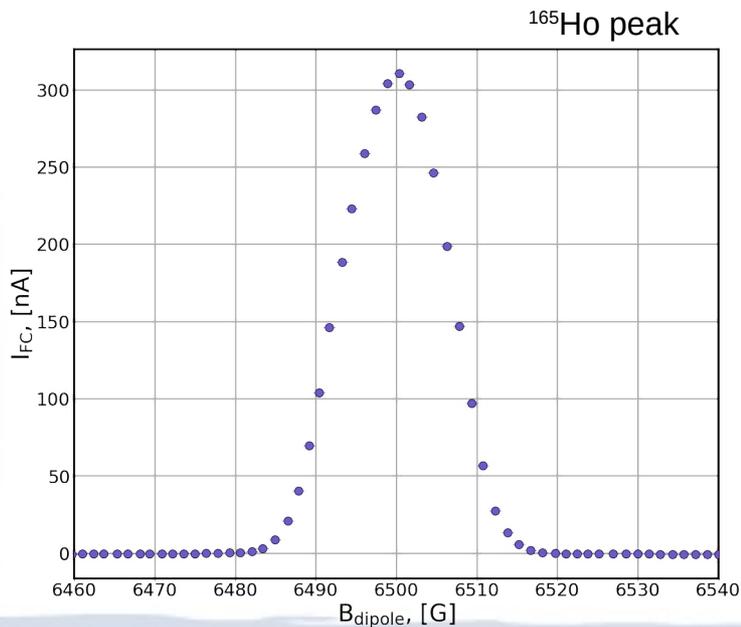
- Sustained  $^{165}\text{Ho}^+$  current  $\text{O}(10 \text{ nA})$ , no signs of extinguishing but the target melted after 7 h run

# Sintered targets (UniGe)

**Sinter  
Zr 95%, Y 5%  
on Ti holder  
with  $\text{Ho}(\text{NO}_3)_3$**



- $^{165}\text{Ho}$  in form of  $\text{Ho}(\text{NO}_3)_3$
- Y chips and Zr fine-grained powder ( $\leq 100 \mu\text{m}$ ) prepared pressed at  $350 \text{ bar/cm}^2$
- baked at  $950 \text{ }^\circ\text{C}$  and at  $10^{-4} \text{ mbar}$  (low-oxygen environment) for 3 hours.
- $\text{Ho}(\text{NO}_3)_3$  deposited on the Zr-Y sinter and dried on a hot plate in Ar atmosphere to avoid oxidation
- Ti holder for better sinter attachment



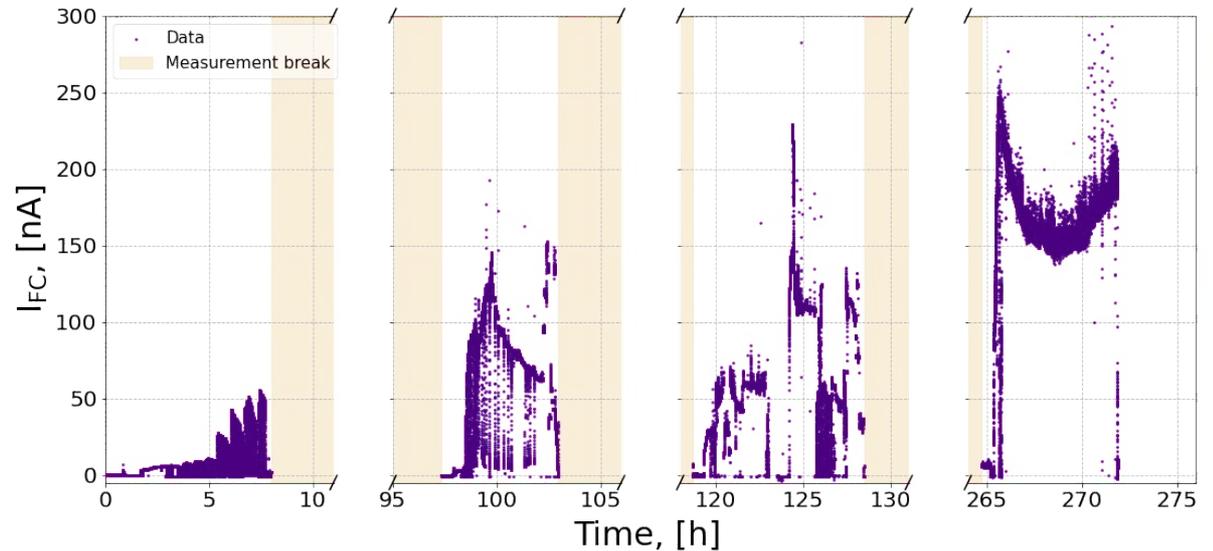
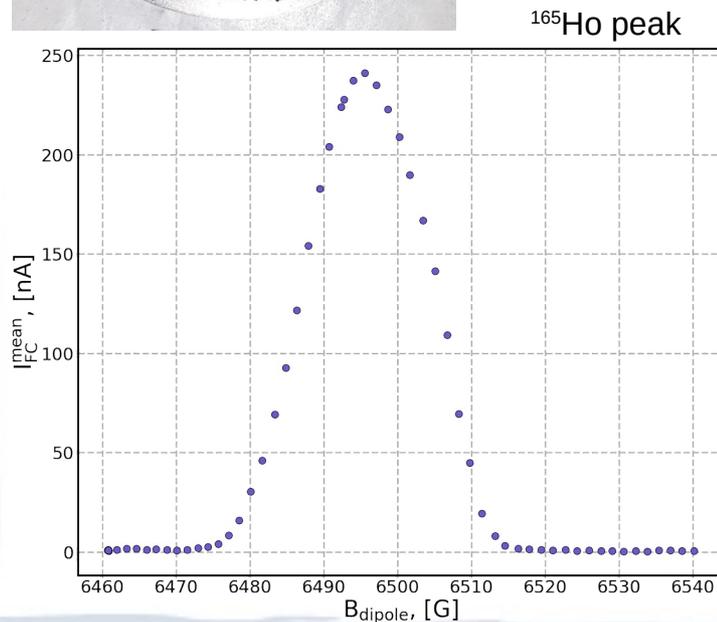
- $\text{O}(200 \text{ nA} - 1 \mu\text{A})$   $^{165}\text{Ho}^+$  current sustained over  $\text{O}(15 \text{ h})$

# Sintered targets (UniGe)

**Sinter  
Zr 95%, Y 5%  
on Mo holder  
with  $\text{Ho}(\text{NO}_3)_3$**



- $^{165}\text{Ho}$  in form of  $\text{Ho}(\text{NO}_3)_3$
- Y chips and Zr fine-grained powder ( $\leq 100 \mu\text{m}$ ) prepared pressed at  $350 \text{ bar/cm}^2$
- baked at  $950 \text{ }^\circ\text{C}$  and at  $10^{-4} \text{ mbar}$  (low-oxygen environment) for 3 hours.
- $\text{Ho}(\text{NO}_3)_3$  deposited on the Zr-Y sinter and dried on a hot plate in Ar atmosphere to avoid oxidation
- Mo holder for better thermal properties



- O(100-200 nA)  $^{165}\text{Ho}^+$  current sustained over O(15 h)

# Sintered targets (UniGe)

**Sinter**  
**Zr 95%, Y 5%**  
**on Mo holder**  
**with  $\text{Ho}(\text{NO}_3)_3$**



**Sinter**  
**Zr 95%, Y 5%**  
**on Ti holder**  
**with  $\text{Ho}(\text{NO}_3)_3$**



**Sinter**  
**metallic Ho 5%,**  
**Ti 36%, Ni 41%,**  
**Sn 18%**  
**on Cu holder**



- + Holmium is distributed over the entire thickness of the target
- + Possibility to use various materials to optimize properties
- Careful handling of radioactive powder

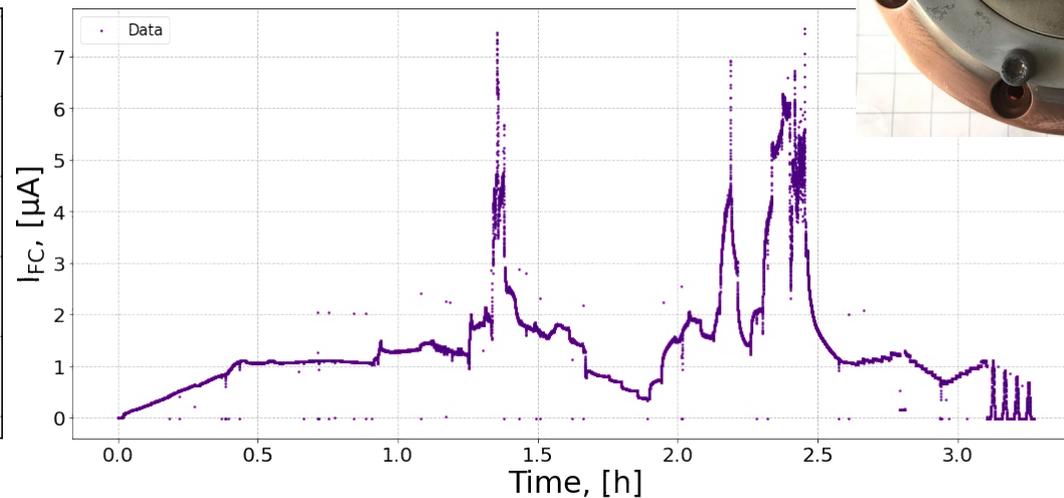
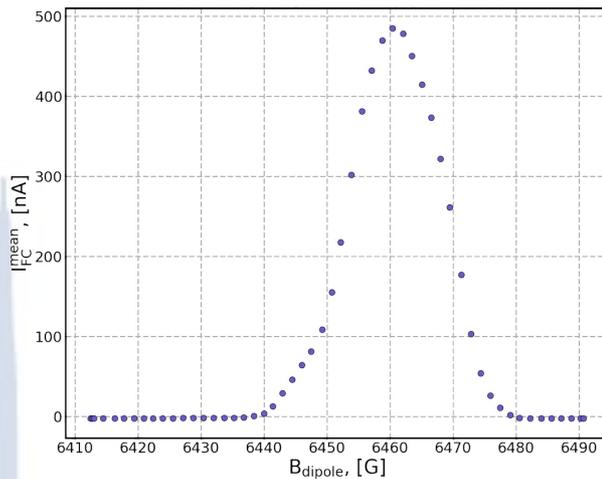
# Other target types

## Ho foils UniGe

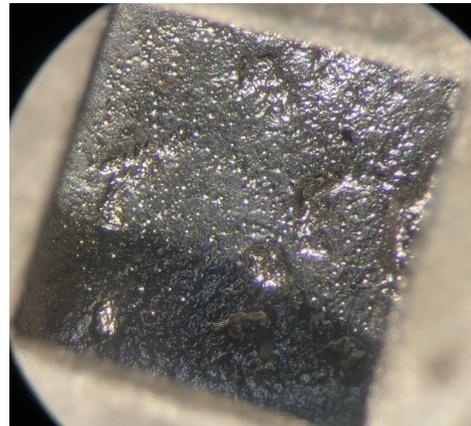
- 4 square pieces of Ho foil ( $\leq 0.5$  g)  
pressed to Bulk Ti holder by a Ti mask  
with 4 square holes correspondingly



$^{165}\text{Ho}$  peak

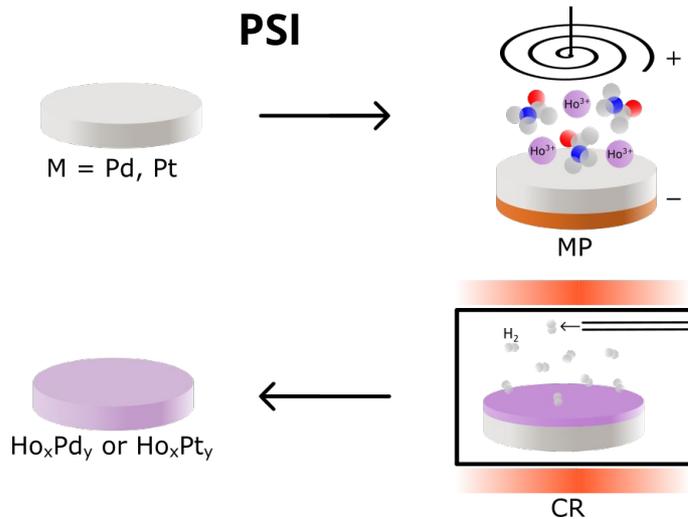


- Current  $O(\mu\text{A})$  current for at least a few hours
- The test was stopped due to a short circuit created inside the source (presumably by a deposit)
- After the test was finished and the source opened, we found the Ti mask deformed;
- Ho foils were welded on the holder and signs of sputtering are seen under the microscope

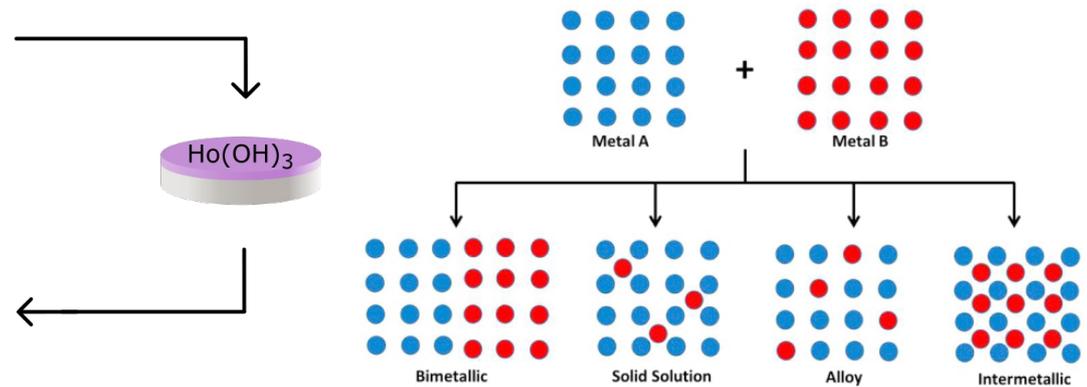


# Other target types

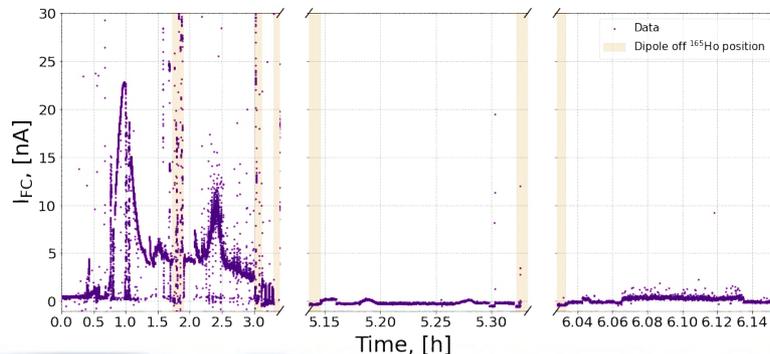
## Coupled reduction (CR) of $\text{Ho}(\text{NO}_3)_3$ on Pd



- Ho reduction and diffusion into backing material due to thermodynamically favourable formation of intermetallic compound



- 2 out of 4 wedges of the Pd substrate with CR Ho fixed with Mo mask used in test

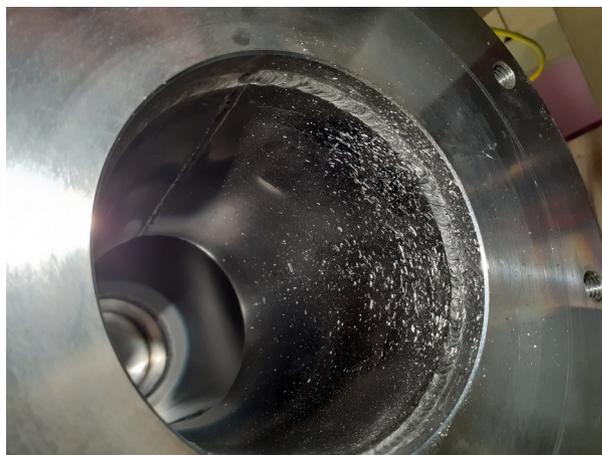


- Initial current  $\sim 23$  nA vanished over  $\sim 5$  h
- Suspect Ho did not diffuse well in Pd  $\rightarrow$  under investigation
- Try encapsulating one of remaining samples in Pt via discharge welding for the next tests

# $^{165}\text{Ho}$ extraction efficiency

Target	$^{165}\text{Ho}$ atoms in target (estimation)	$^{165}\text{Ho}$ atoms extracted (estimation)	Extraction efficiency (lower limit), %
Inkjet printing with acetate	$6 \cdot 10^{18}$	$6.5 \cdot 10^{14}$	0.01
Sinter Zr/Y on Ti holder	$2.3 \cdot 10^{20}$	$1.36 \cdot 10^{17}$	0.06
Sinter Zr/Y on Mo holder	$7 \cdot 10^{19}$	$4.4 \cdot 10^{16}$	0.06
Coupled reduction on Pd	$4.4 \cdot 10^{18}$	$12.7 \cdot 10^{13}$	0.003

Opening the source after tests, we find a lot of target material deposit inside the chamber



# Summary

## **NuMass 2020:**

- finished production and purification and stored 110 MBq of  $^{163}\text{Ho}$
- done first test of the implanter setup with dummy copper target

## **NuMass 2022:**

- The ion source with the reduced implantation beamline has been commissioned and showed a good performance – extraction of ion beams of different materials present in the source chamber.
  - Calibration procedure is established, we can correct for misalignment and estimate beam size, more detailed investigations and comparison with simulations are ongoing.
  - Look for optimal sputter target candidate, ideally chemically pure, having homogeneous distribution of Ho and provide a slow and constant Ho release (and obtained with high yield)
  - Tests with different natural  $^{165}\text{Ho}$ -containing targets show clear peak to 165 a.m.u.:
    - MP, IJP: current stability not satisfactory, 50 nA at max
    - Sinter and Ho foil: sustain high current over O(15 hours), higher currents achievable
- targets with Ho distributed over the target volume work significantly better than superficial Ho

# Outlook

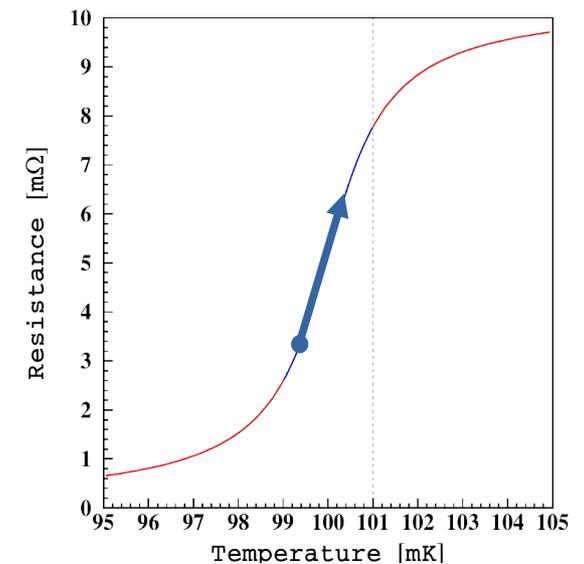
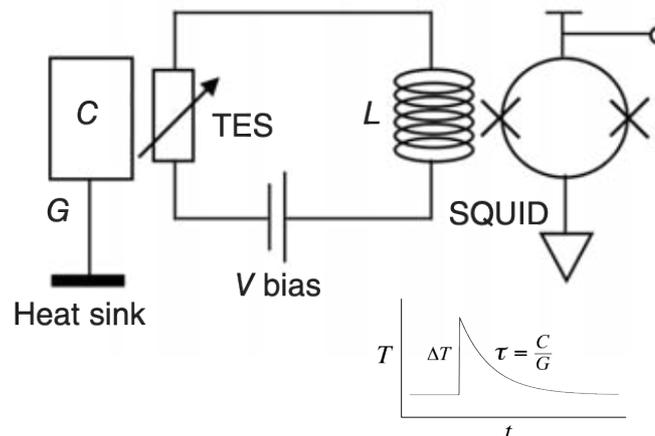
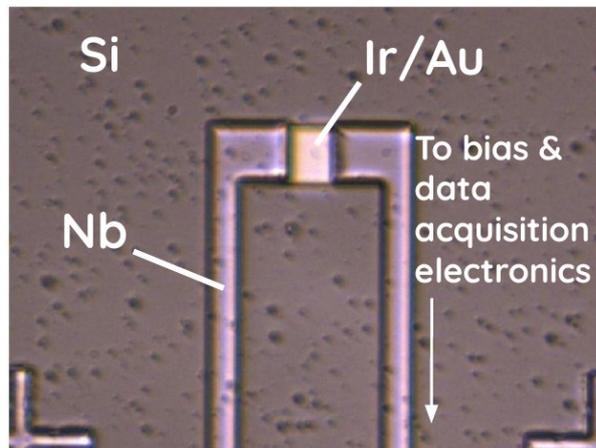
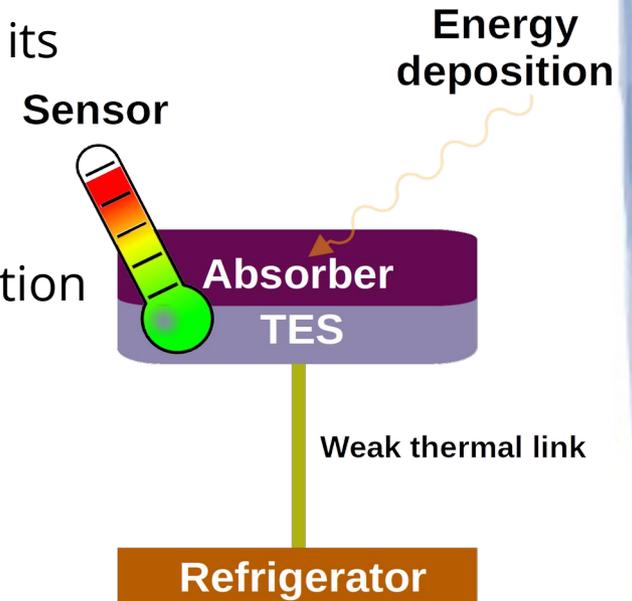
- Better understanding of implanter setup, source tuning to control better power dissipation on sputter target and decrease its working temperature, and effect of the source parameters on the beam profile
- A more detailed analysis of the data already acquired from various targets is ongoing
- Tests of several new types Ho-containing targets (e.g. CR Ho melted inside Pt drops; combine sinter + IJP + CR) to find the optimal one in terms of Ho extraction efficiency/handling
- After the optimal target is chosen, implant a detector array with low dose of  $^{163}\text{Ho}$  ( $\sim 1$  Bq/det)

Thanks for your attention!

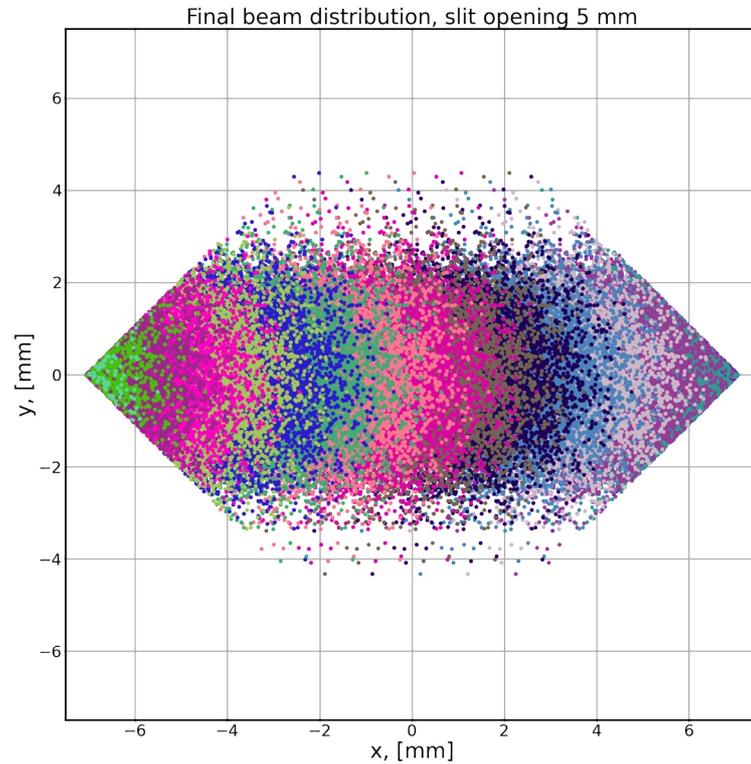
# TES detectors

## Transition Edge Sensor (TES):

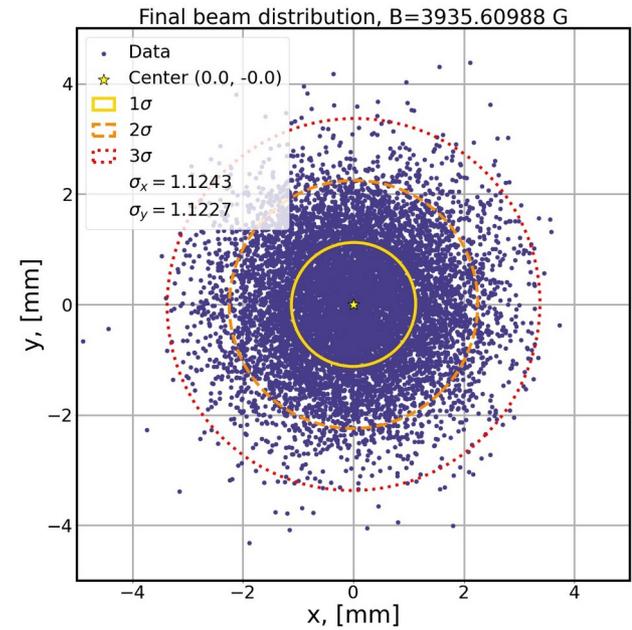
- sensitive film thermometer operated below and close to its transition (critical) temperature  $T_c$  (sub-K)
- energy deposited onto TES is transformed to heat which increases TES resistance.
- steep change of resistance with temperature, low operation temperature and narrow bandgap of superconductors => high sensitivity for different applications
- change in resistance causes change in current flowing through TES. This change is read out by a SQUID.



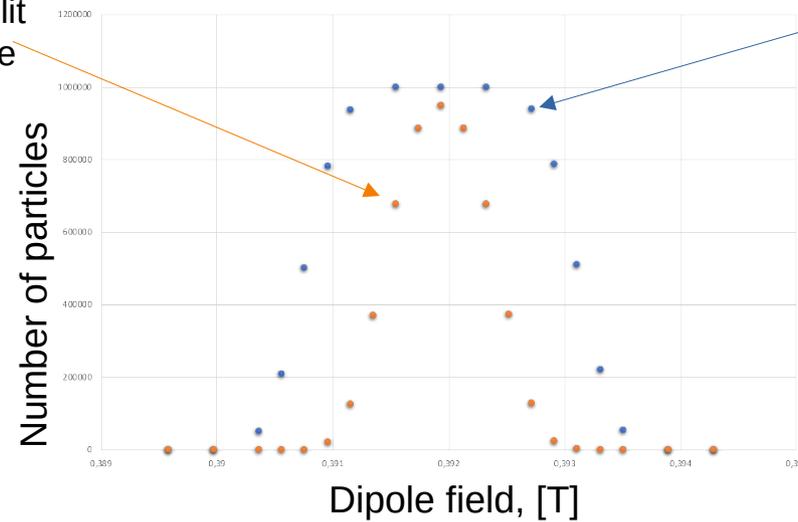
# Simulation of ion beam in *elegant* software



- Magnetic field
- 3915.9318306 G
  - 3917.89963554 G
  - 3919.86744048 G
  - 3921.83524542 G
  - 3923.80305036 G
  - 3925.770855299998 G
  - 3927.73866024 G
  - 3929.70646518 G
  - 3931.67427012 G
  - 3933.64207506 G
  - 3935.60988 G
  - 3937.5776849400004 G
  - 3939.54548988 G
  - 3941.51329482 G
  - 3943.4810997600002 G
  - 3945.4489047 G
  - 3947.41670964 G
  - 3949.38451458 G
  - 3951.35231952 G
  - 3953.3201244600004 G
  - 3955.2879294 G

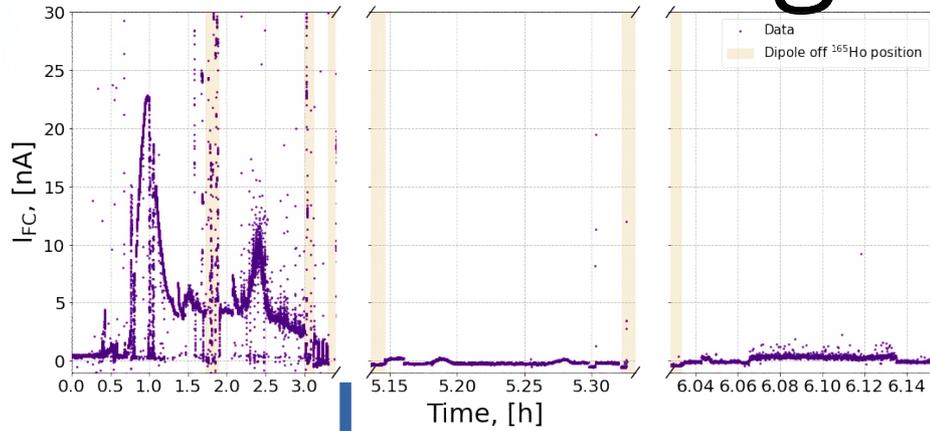


5 mm slit aperture

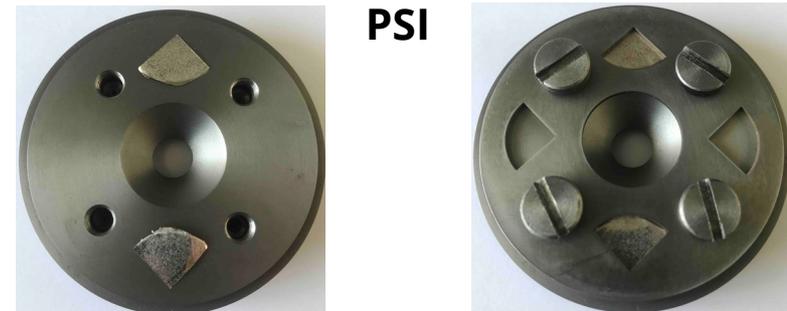


10 mm slit aperture

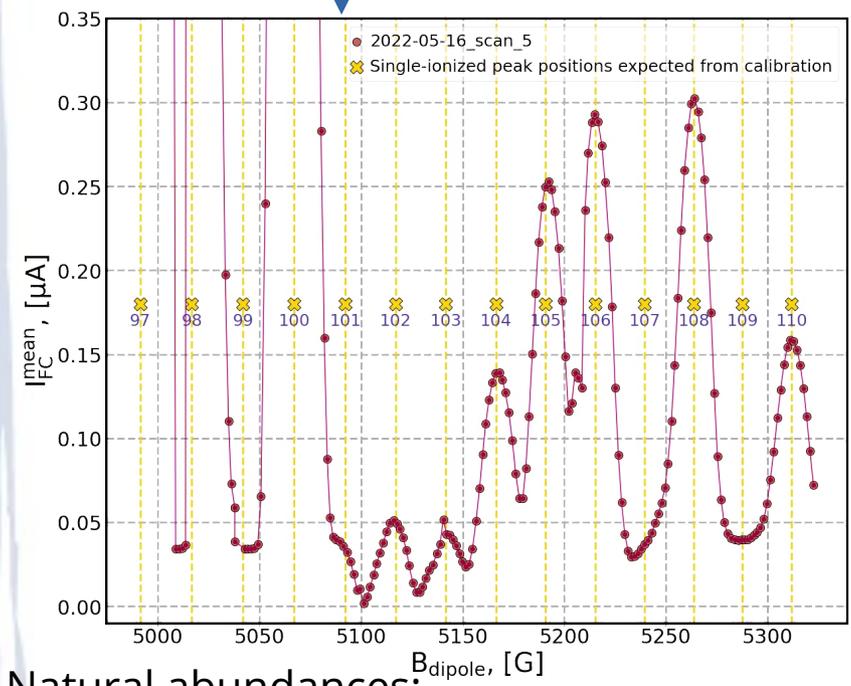
# Different target types with $^{165}\text{Ho}$



## Coupled reduction of $\text{Ho}(\text{NO}_3)_3$ on Pd



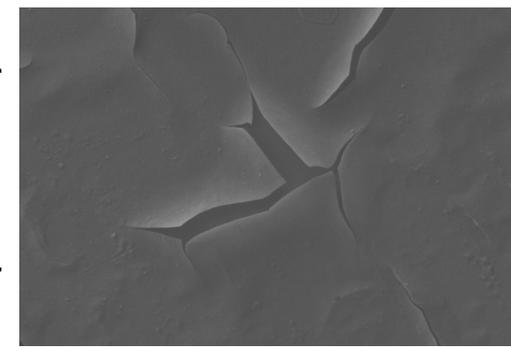
Characterization of test sample (not target)



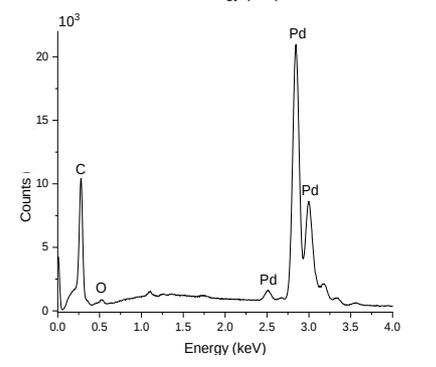
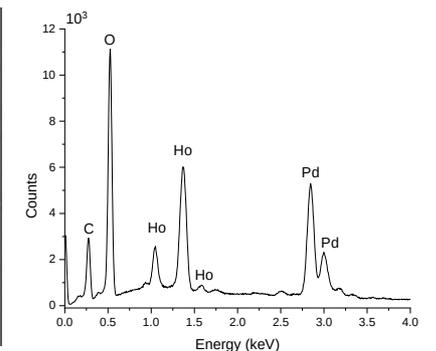
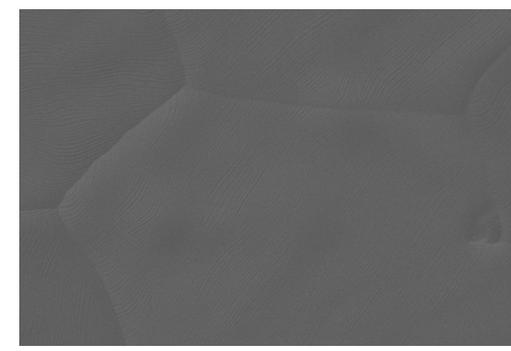
Natural abundances:

$^{92}\text{Mo}$ : 14.84%	$^{94}\text{Mo}$ : 9.25%	$^{95}\text{Mo}$ : 15.92%	$^{96}\text{Mo}$ : 16.68%	$^{97}\text{Mo}$ : 9.55%	$^{98}\text{Mo}$ : 24.13%	$^{100}\text{Mo}$ : 9.63%
$^{102}\text{Pd}$ : 1.02%	$^{104}\text{Pd}$ : 11.14%	$^{105}\text{Pd}$ : 22.33%	$^{106}\text{Pd}$ : 27.33%	$^{108}\text{Pd}$ : 26.46%	$^{110}\text{Pd}$ : 11.72%	

Before CR  
(after MP)



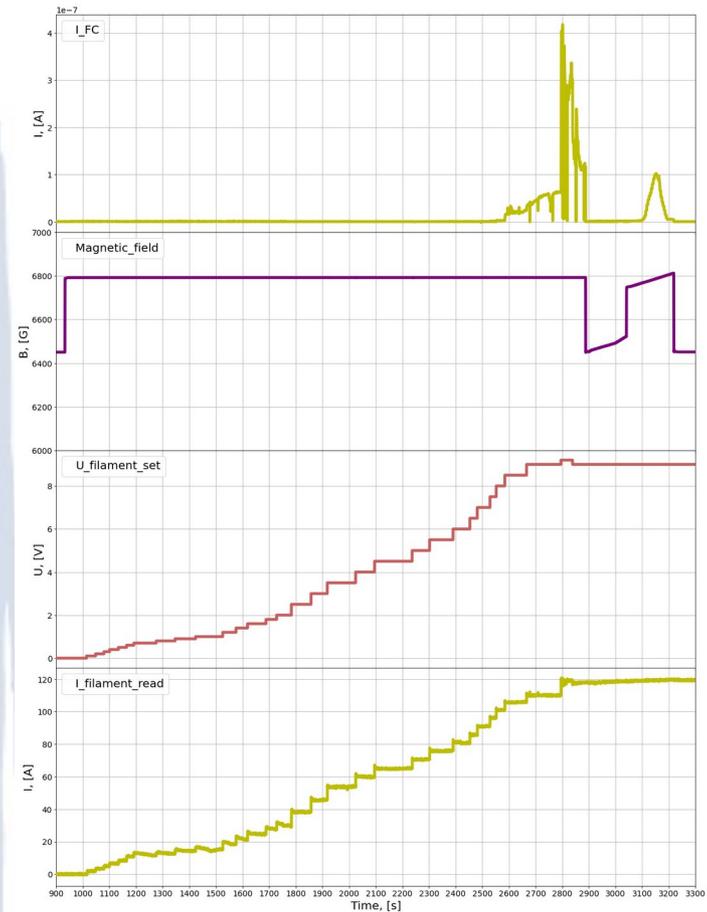
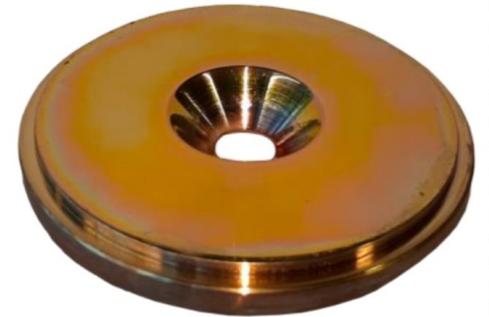
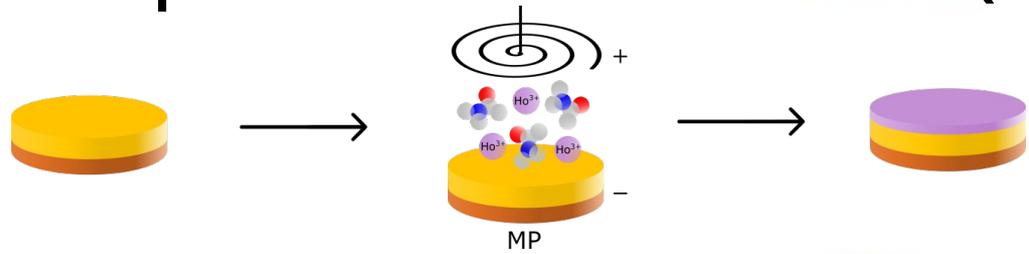
After CR



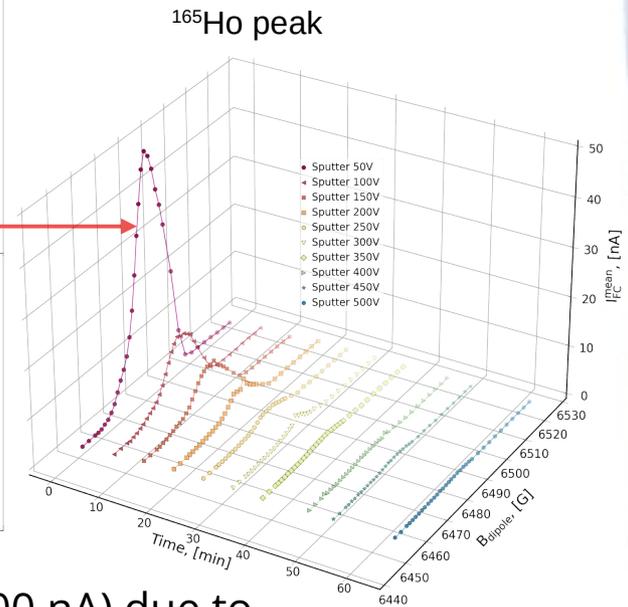
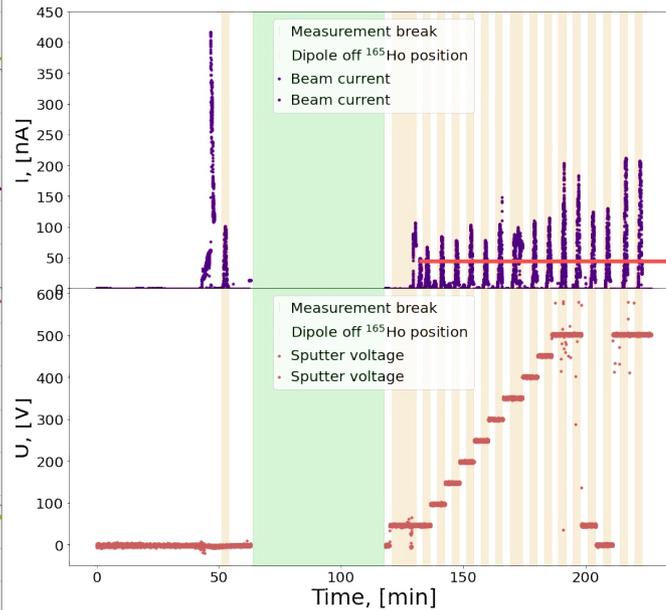
# Targets with $^{165}\text{Ho}$ compound on surface (PSI)

Molecular plating (MP)  
 $\text{Ho}(\text{OH})_3$   
PSI

- deposition of Ho complexes in an organic solvent at high voltages with high uniformity and efficiency

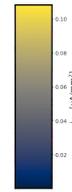
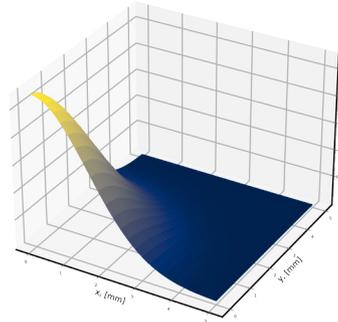
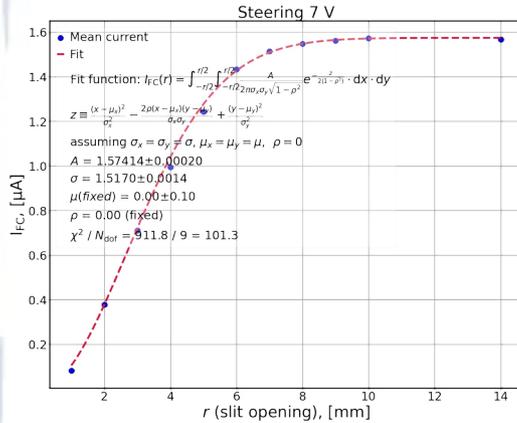


Sample 2:  
Au 100 nm + Ti 18 nm sticking layer  
on Cu bulk



- Initial  $^{165}\text{Ho}^+$  current spike O(400 nA) due to filament warming, then from ~50 nA vanishing over 30 min

# Fit of the slit aperture scan data



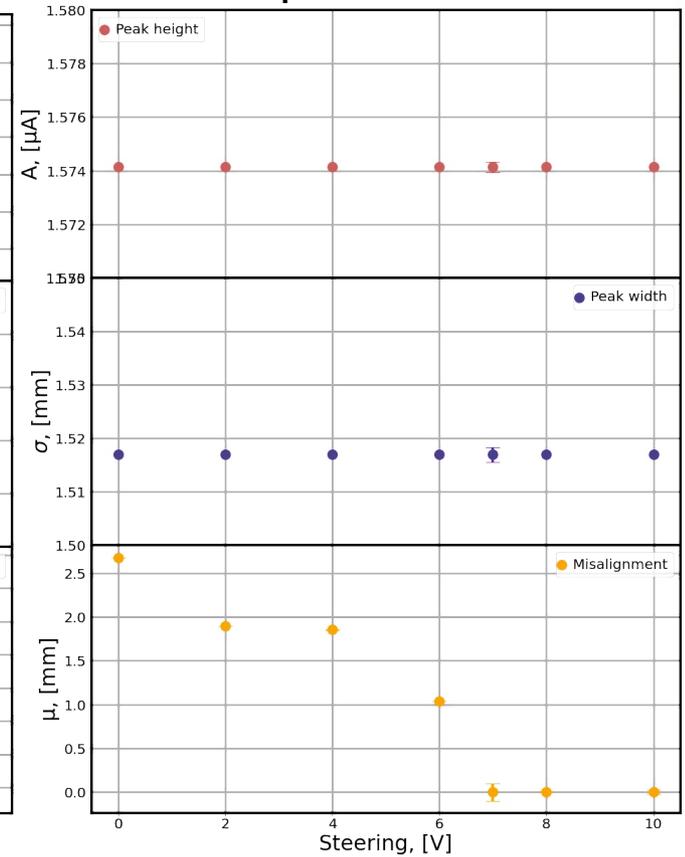
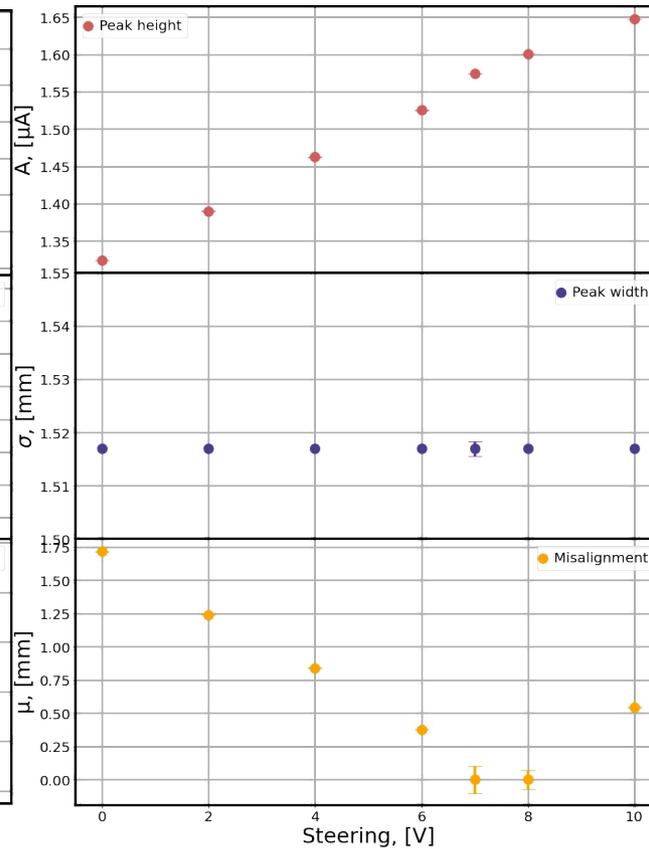
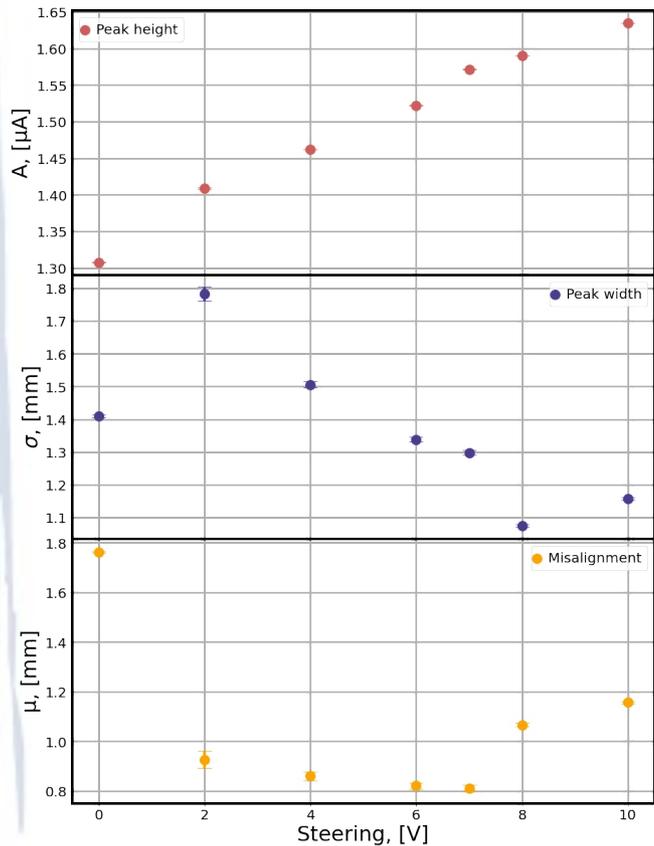
7V: fixed  $\mu=0$   
 $\rightarrow \sigma$

7V: fixed  $\mu=0$   
 $\rightarrow A, \sigma$

other settings:  
 $\sigma$  fixed from 7V,  
A and  $\mu$  free

other settings:  
 $\sigma, A$  fixed from 7V,  
 $\mu$  free

A,  $\sigma$ ,  $\mu$  free



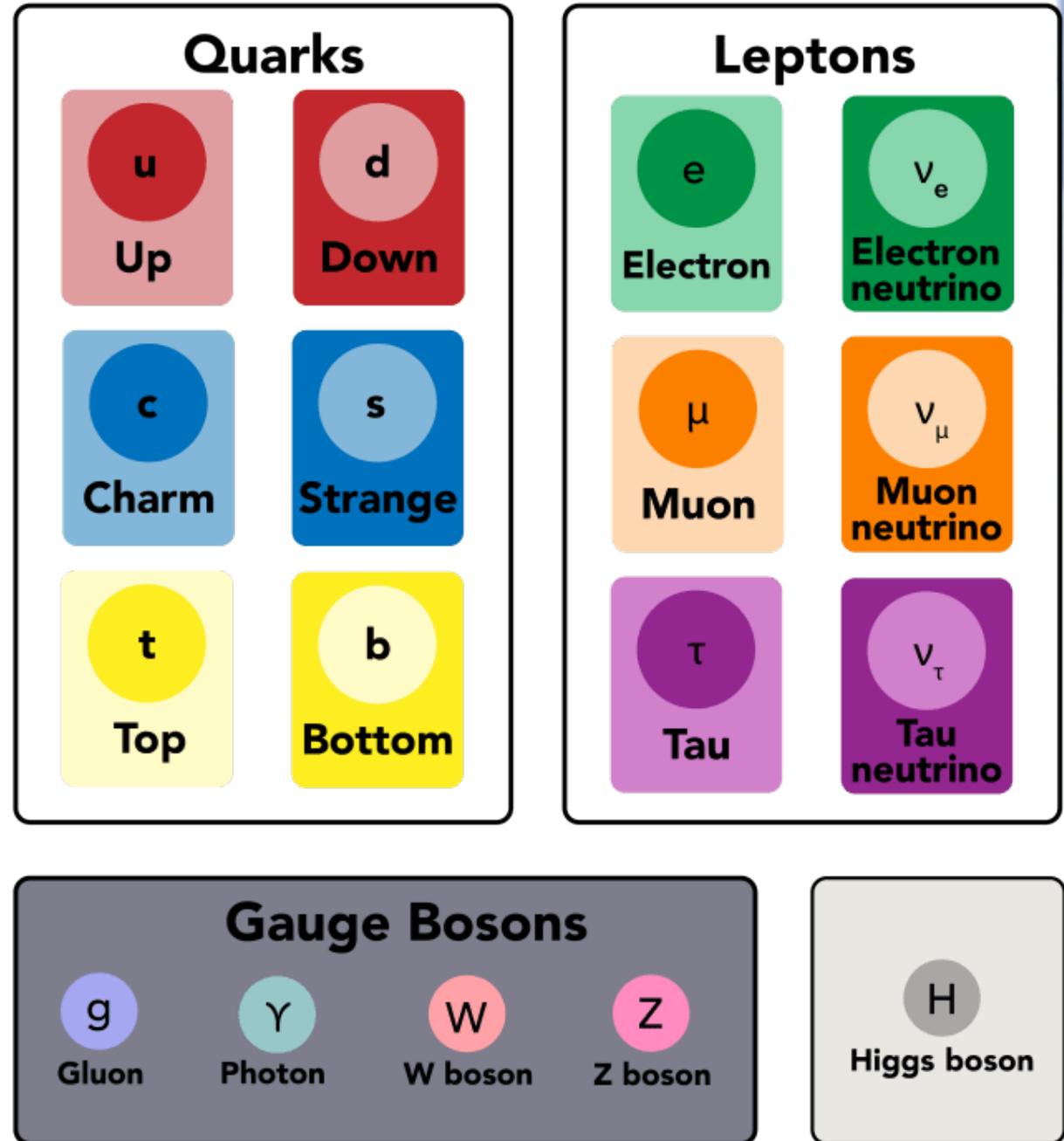
# Neutrinos in the Standard Model

Neutrinos in Standard Model:

- Massless
- Left-handed
- Only weak interactions (no electromagnetic, strong)
- 3 flavour states:  $\nu_e, \nu_\mu, \nu_\tau$

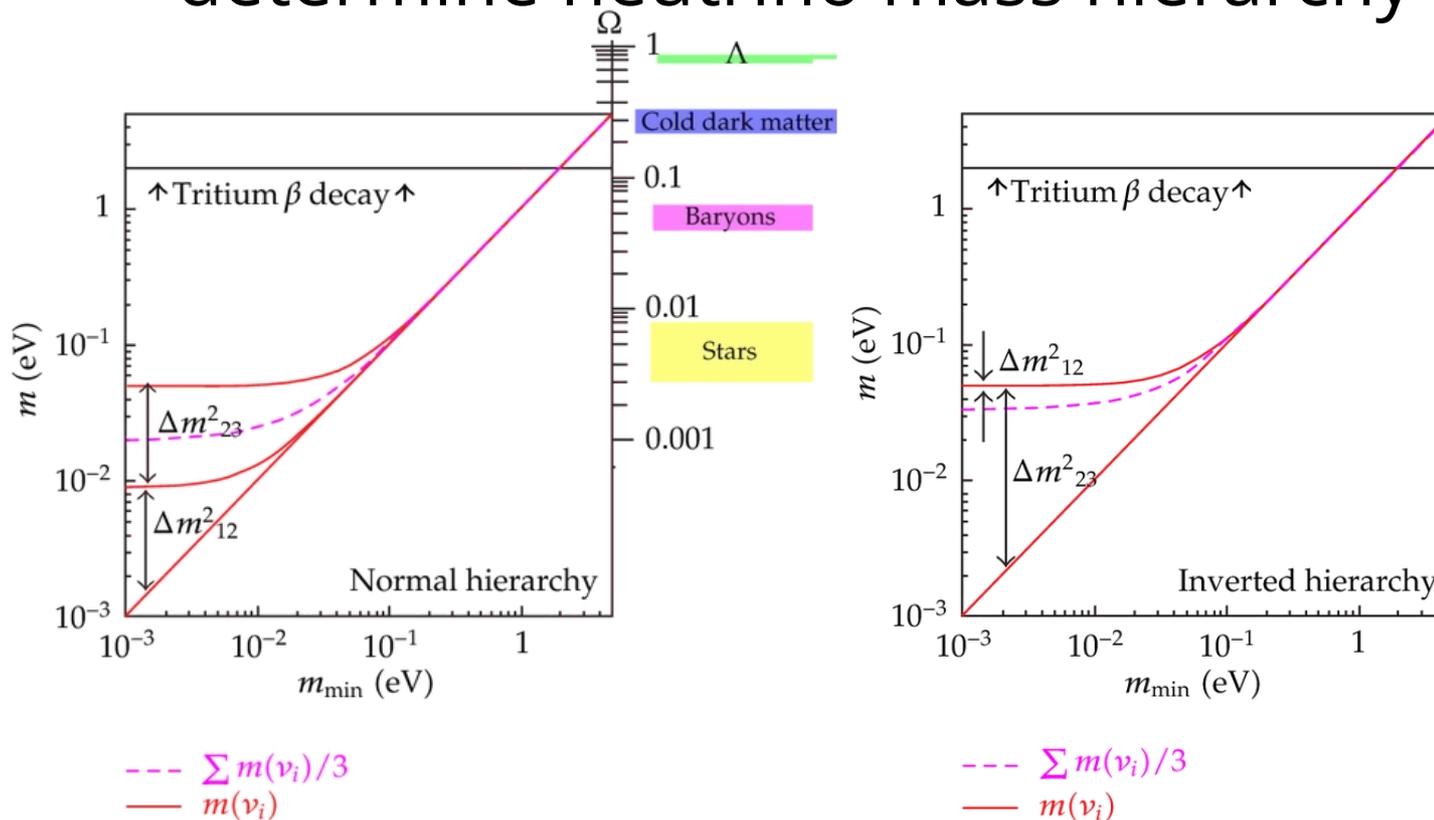
Beyond the Standard Model:

- Neutrino oscillation experiments:  
neutrinos have mass  
(no knowledge on the absolute scale)



# Why measuring neutrino mass?

- origin of fermion masses
- Standard Model extension
- important parameter in cosmology
- determine neutrino mass hierarchy

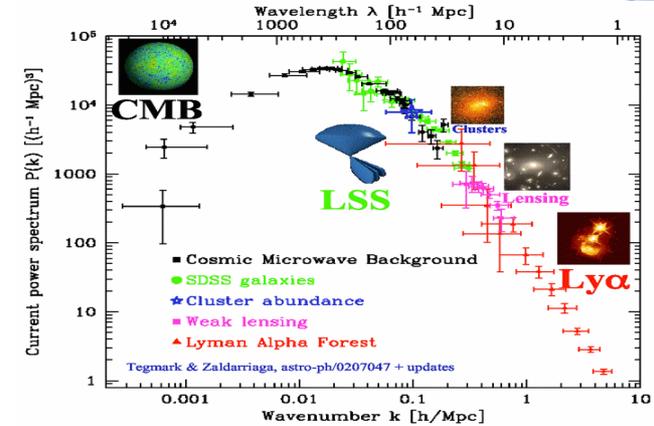
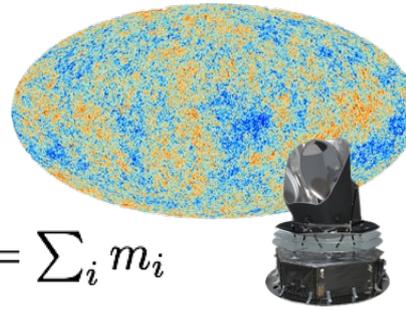


# 3 ways to probe neutrino mass

## Cosmology

- Very sensitive, but model-dependent
- Present upper limit: 0.12 eV – 0.26 eV

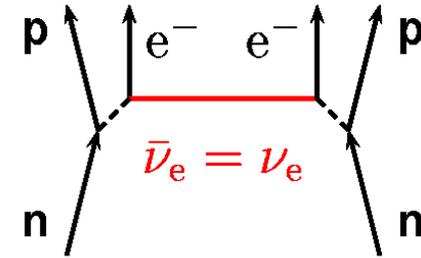
$$M_\nu = \sum_i m_i$$



## $0\nu\beta\beta$ decay

- Sensitive to Majorana neutrinos, model dependent
- Present upper limit 0.12-0.4 eV

$$m_{\beta\beta}^2 = \left| \sum_i U_{ei}^2 m_i \right|^2$$



## Direct measurement

- Use  $E^2 = p^2c^2 + m^2c^4 \rightarrow m^2(\nu)$
- Time-of-flight measurements from supernova, model-dependent...
- SN1987a (Large Magellan Cloud) :  $m(\nu_e) < 5.8$  eV
- Kinematics of weak decays/  $\beta$ -decays - model independent!
- $\beta$ -decay searches for  $m(\nu_e)$  :
  - tritium (KATRIN)
  - $^{163}\text{Ho}$  electron capture (ECHO, HOLMES, and NuMECS)
- Present upper limit: 1.1 eV (KATRIN)

$$m_\beta^2 = \sum_i |U_{ei}|^2 m_i^2$$

